

Agenda



Introdução



Fundamentos de
AOC



Sistema
Computacional



Dispositivos de
E/S

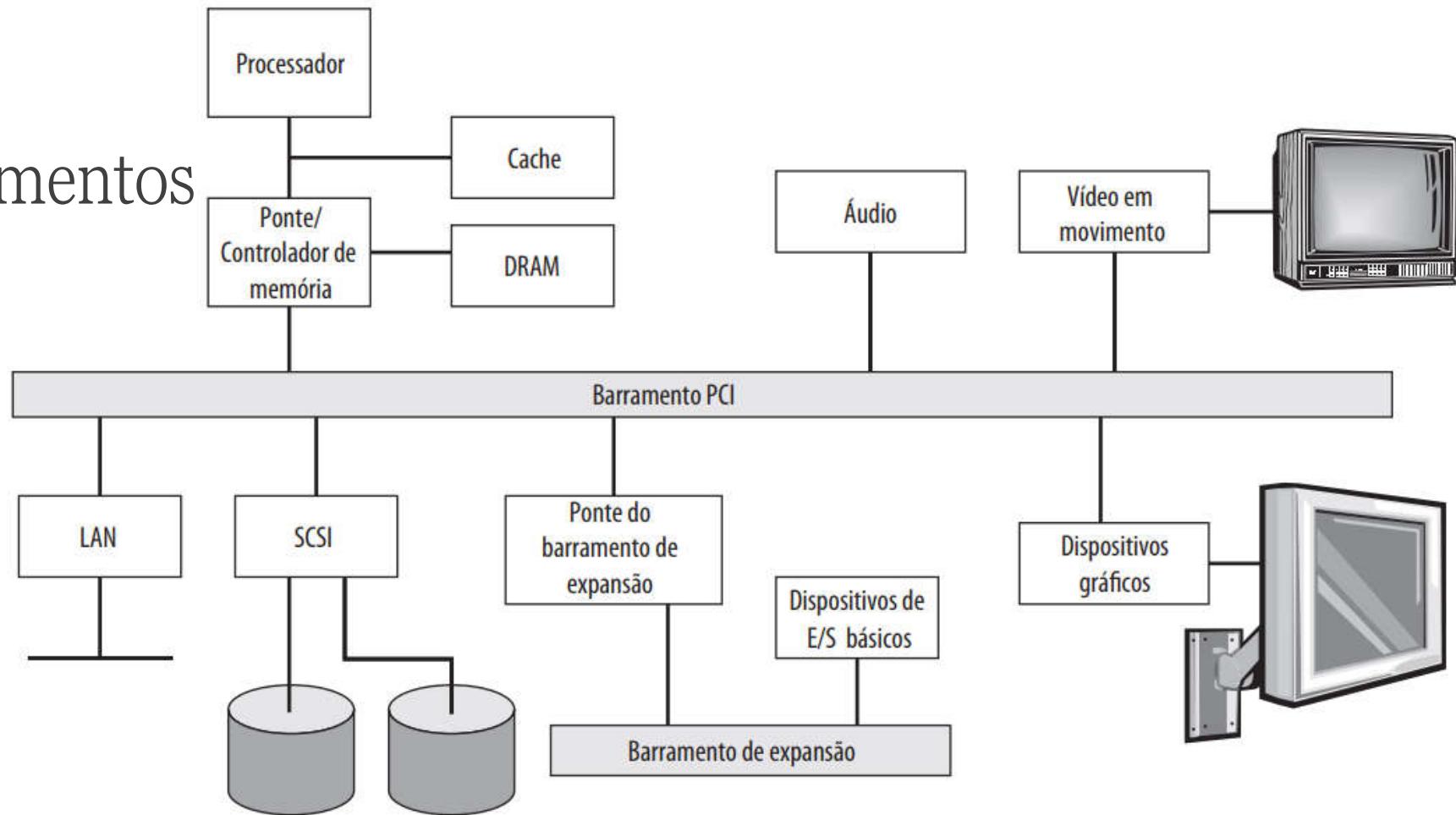


Armazenamento
de Dados



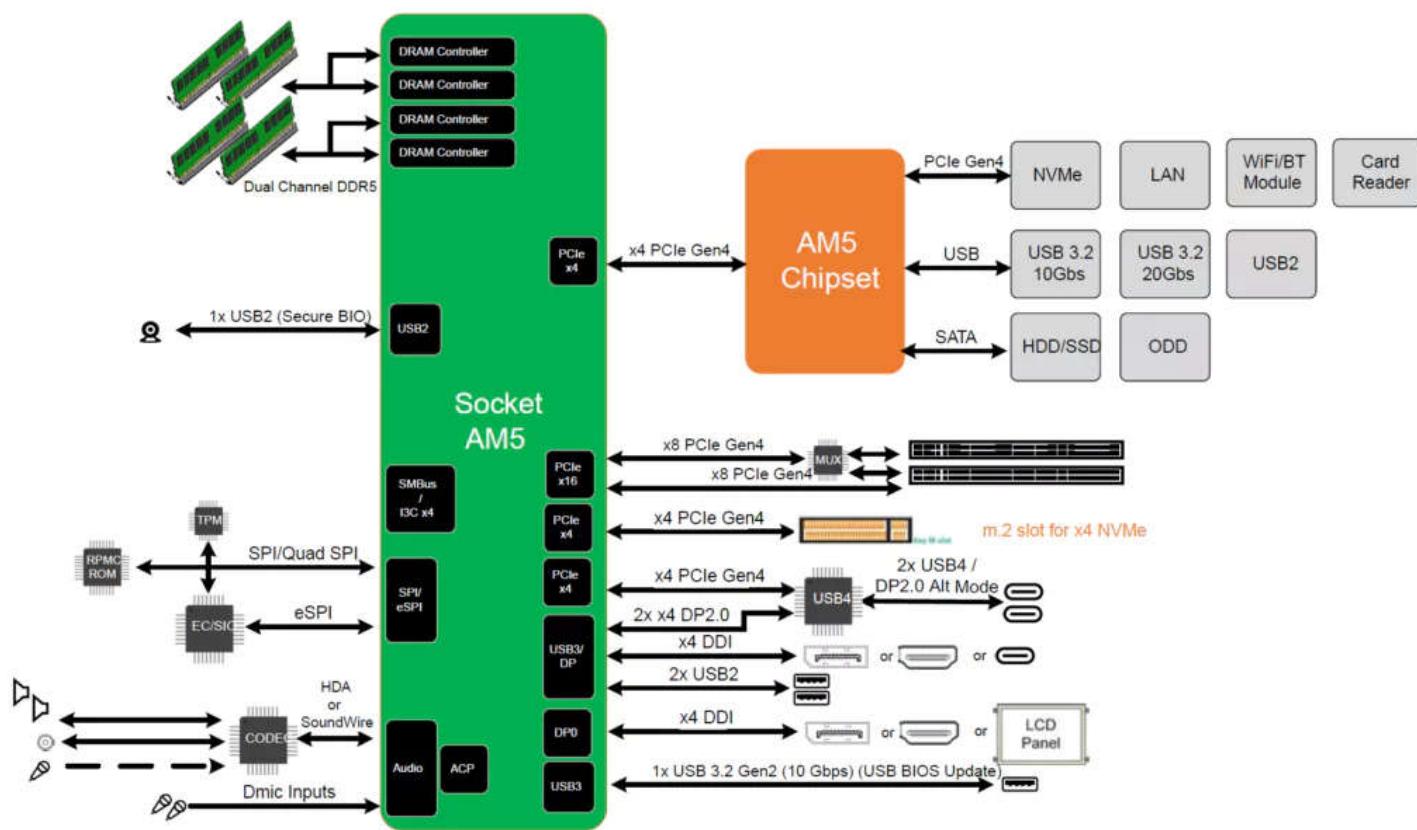
Processamento
da Dados

Barramentos



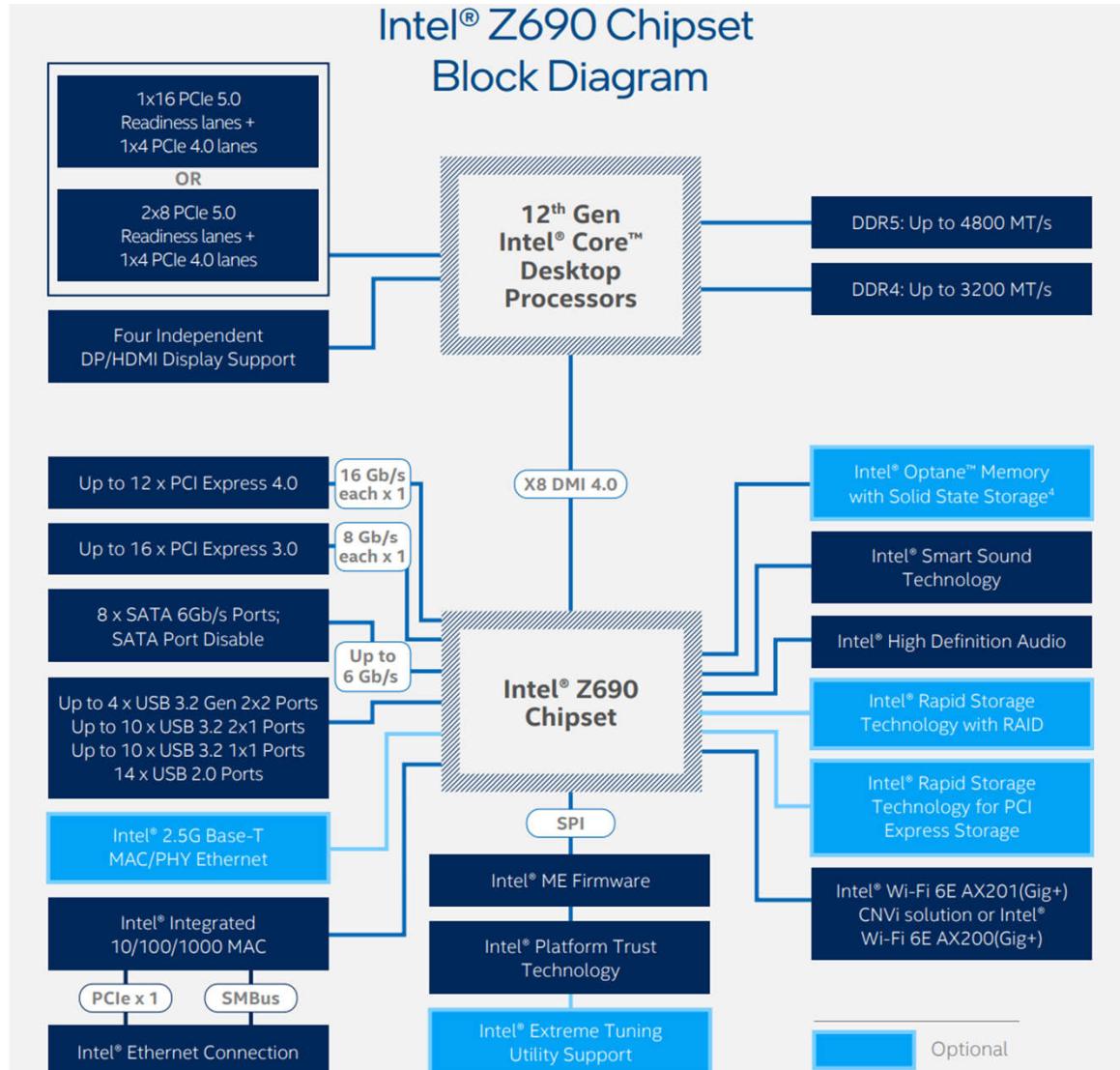
Chipset AMD

- AMD 600-series
 - 3 chipsets: X670E, X670 e B650
 - [Link](#)



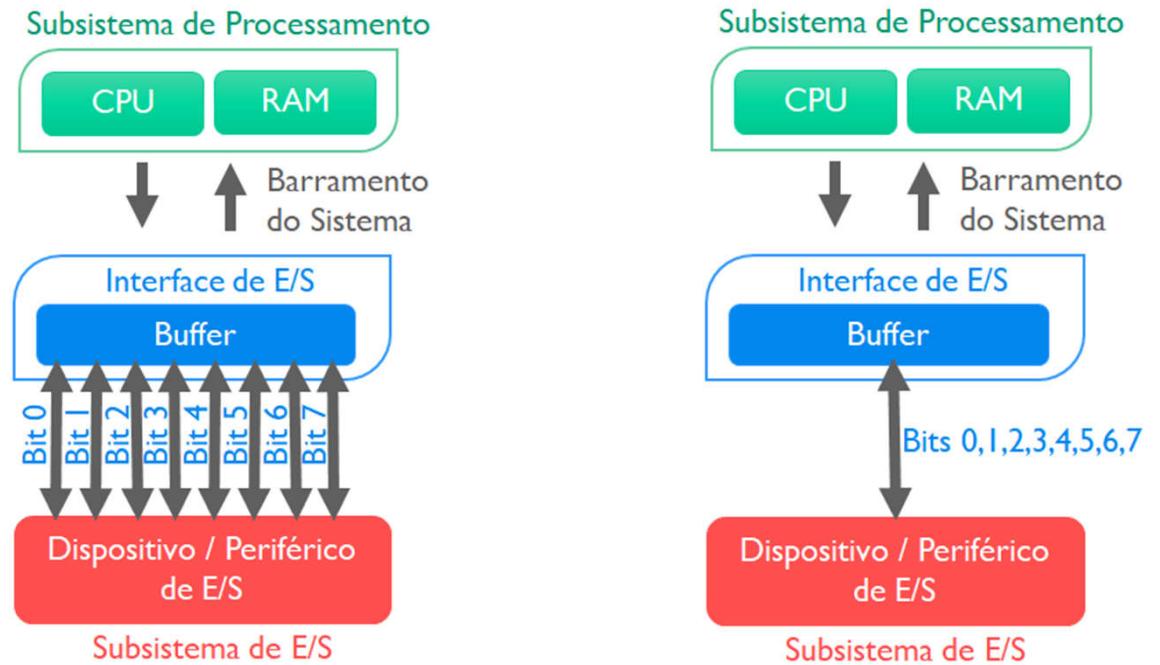
Chipset Intel

- Intel core i9
 - 12 Gen
- Chipset Intel Z690



Comunicação

- Paralelo
- Serial

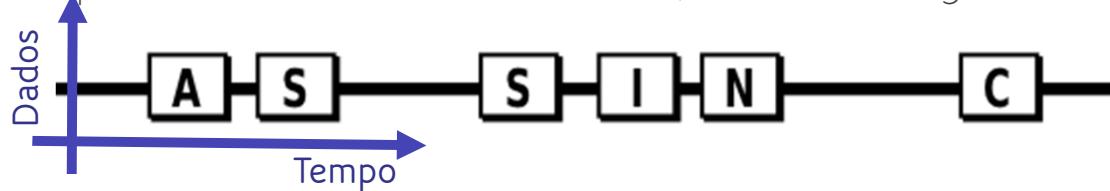


Característica	Paralelo	Serial
Custo	Maior	Menor
Distância	Curta	Sem Limite
Vazão (Throughput)	Alto	Baixo

Transmissão

- Transmissão Assíncrona

- O tempo entre os dados enviados é variável, tornando a chegada da informação não previsível



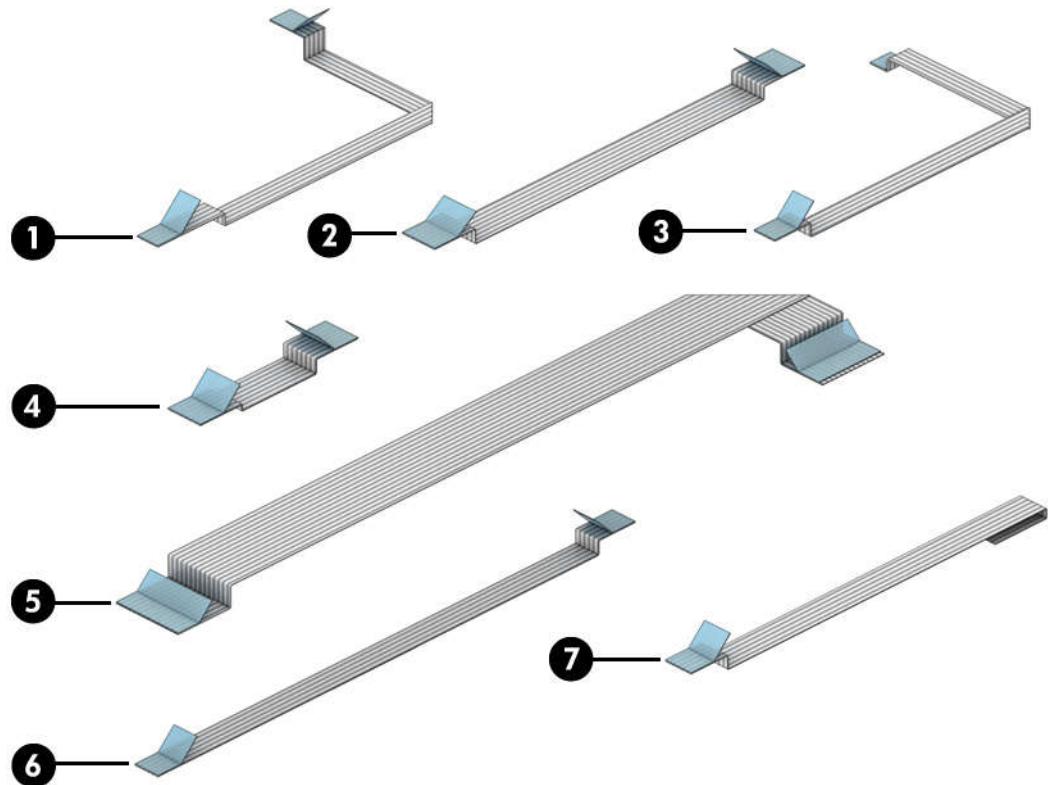
- Transmissão Síncrona

- O tempo entre os dados enviados é constante, pode-se prever a chegada da informação

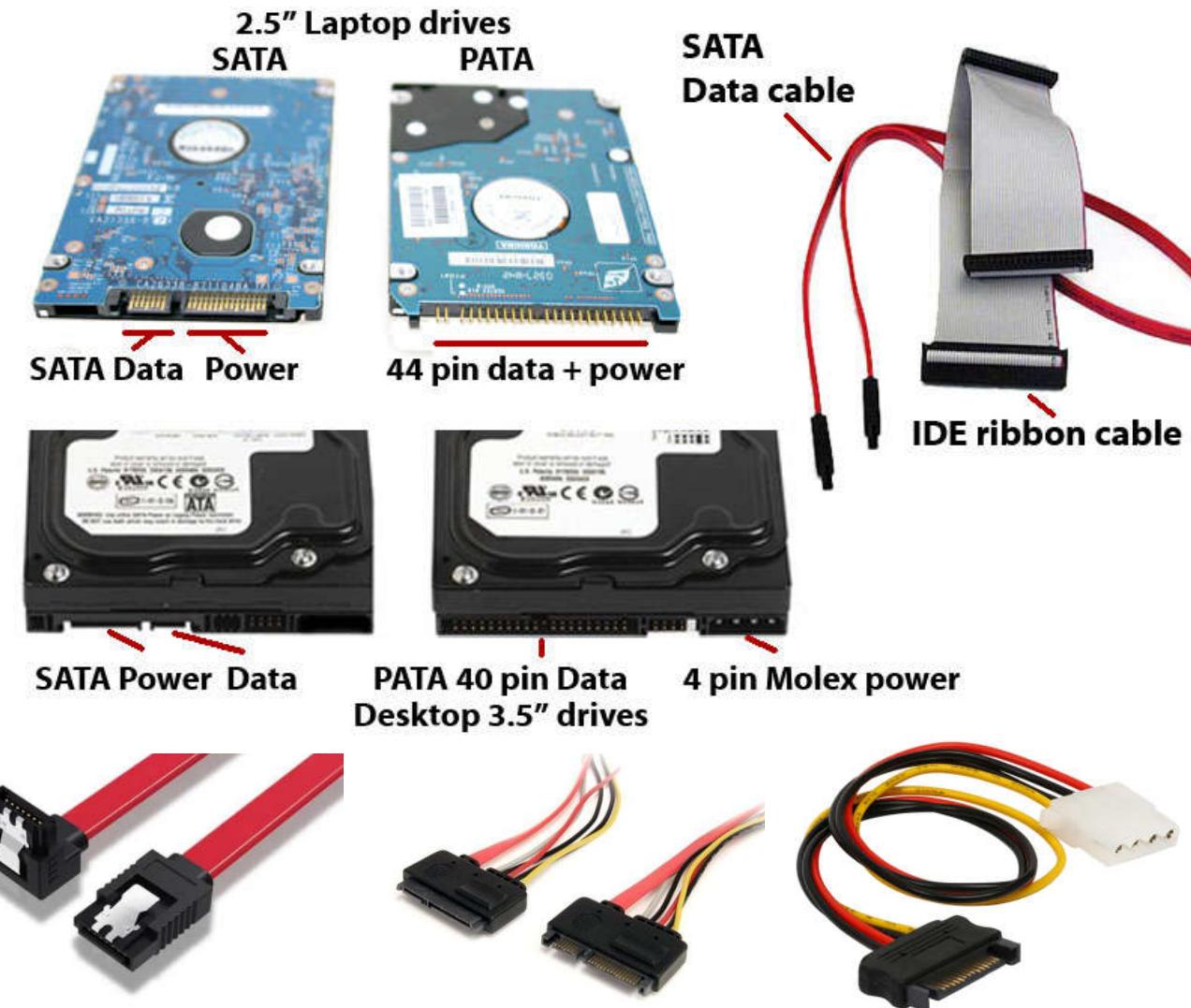
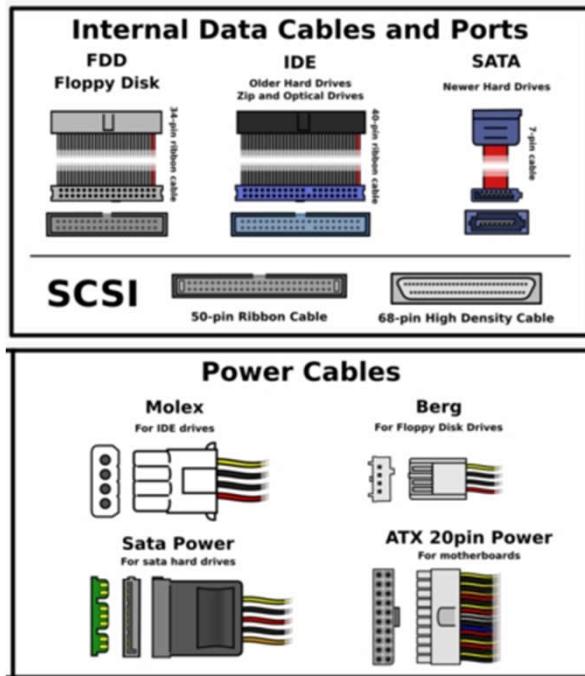


Cabos Notebook

1. Cabo do HD/SSD
2. Cabo da placa usb
3. Cabo do áudio
4. Cabo do leitor de cartão
5. Cabo do leitor Biométrico
6. Cabo dos botões do touchpad
7. Cabo do touchpad



Cabos Desktop PATA vs SATA

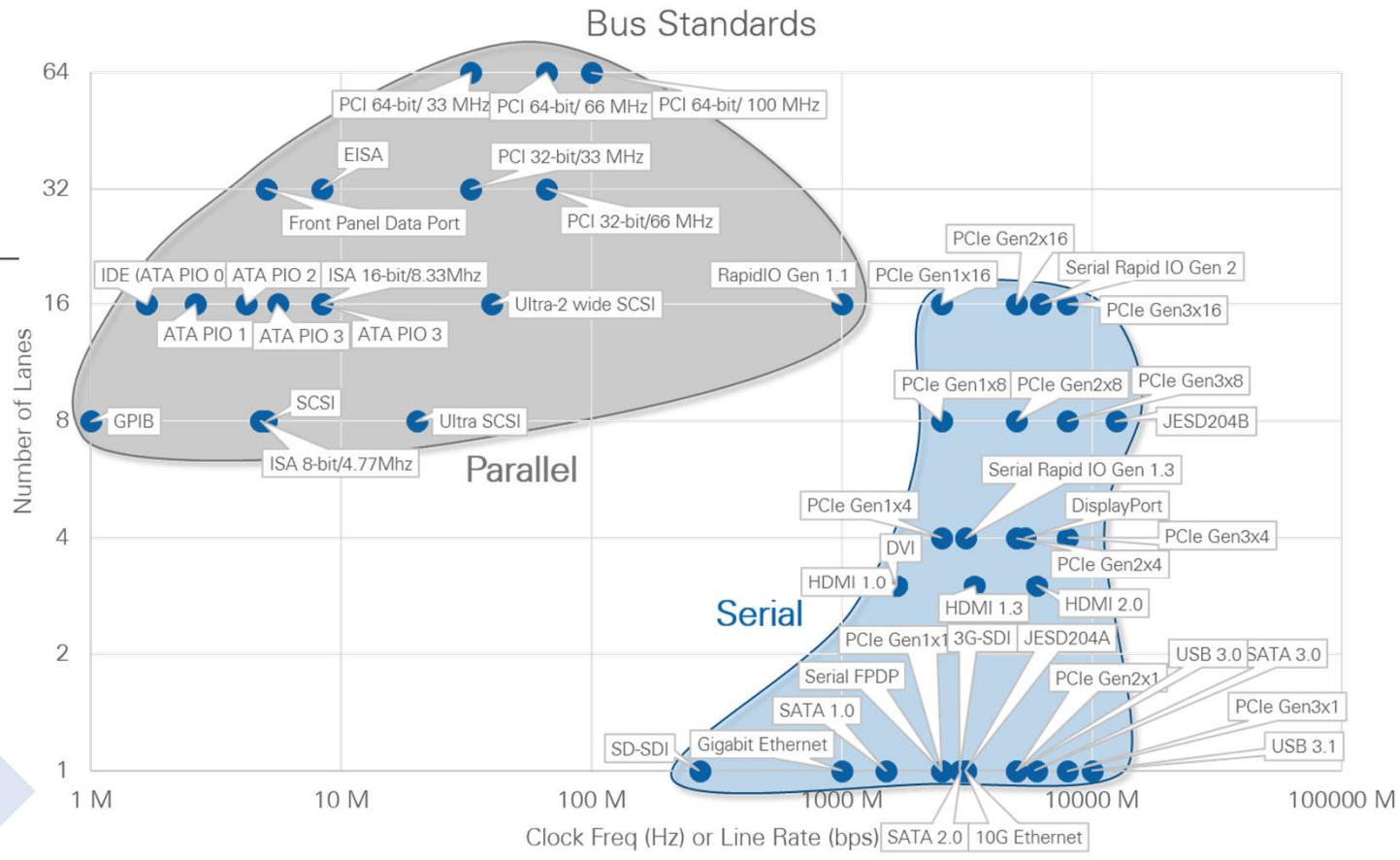
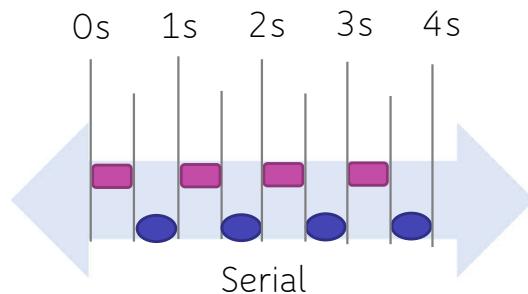


[QUILL, 2012]

UNEMAT

Barramentos

- Serial
- Paralelo



SSD Class

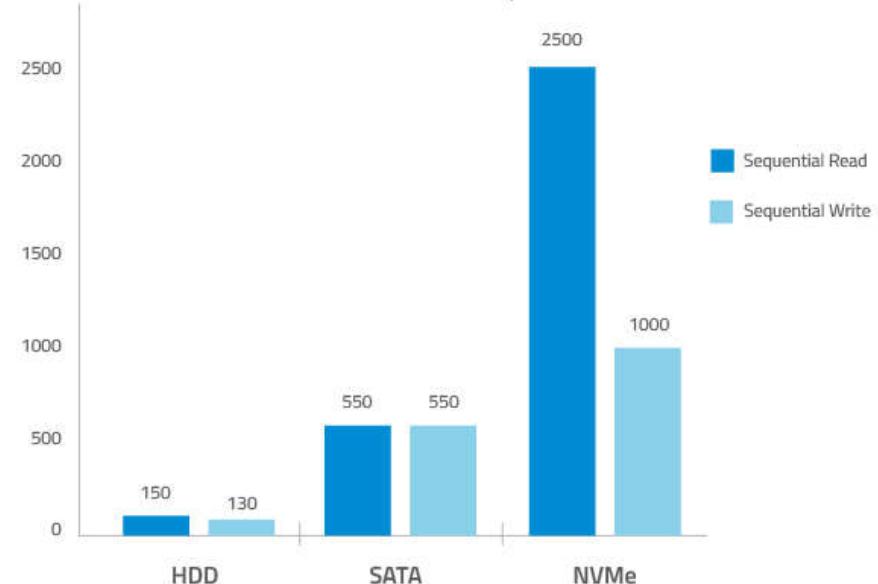
	Class	Sequential* Read/Write	Random** Read/Write	Interface
SATA	10 "value"	520K/320K	30K/10K	SATA interface reduced features e.g. dram-less <i>Consumer Offering</i>
	20 "mainstream"	500K/300K	80K/60K	SATA Interface full feature set <i>Consumer, Commercial</i>
	30 "performance"	550K/350K	90K/75K	Best in class SATA <i>Precision Only</i>
PCIe	40 "performance"	1500/350K	200K/80K	PCIe interface NVMe host protocol <i>Consumer, Commercial Performance</i>
	50 "performance"	2100K/1200K	300K/100K	Best in class PCIe <i>Precision Only</i>



[DELL, 2018]

Sata x Nvme

HDD vs. SATA vs. NVMe
Maximum Theoretical Speeds

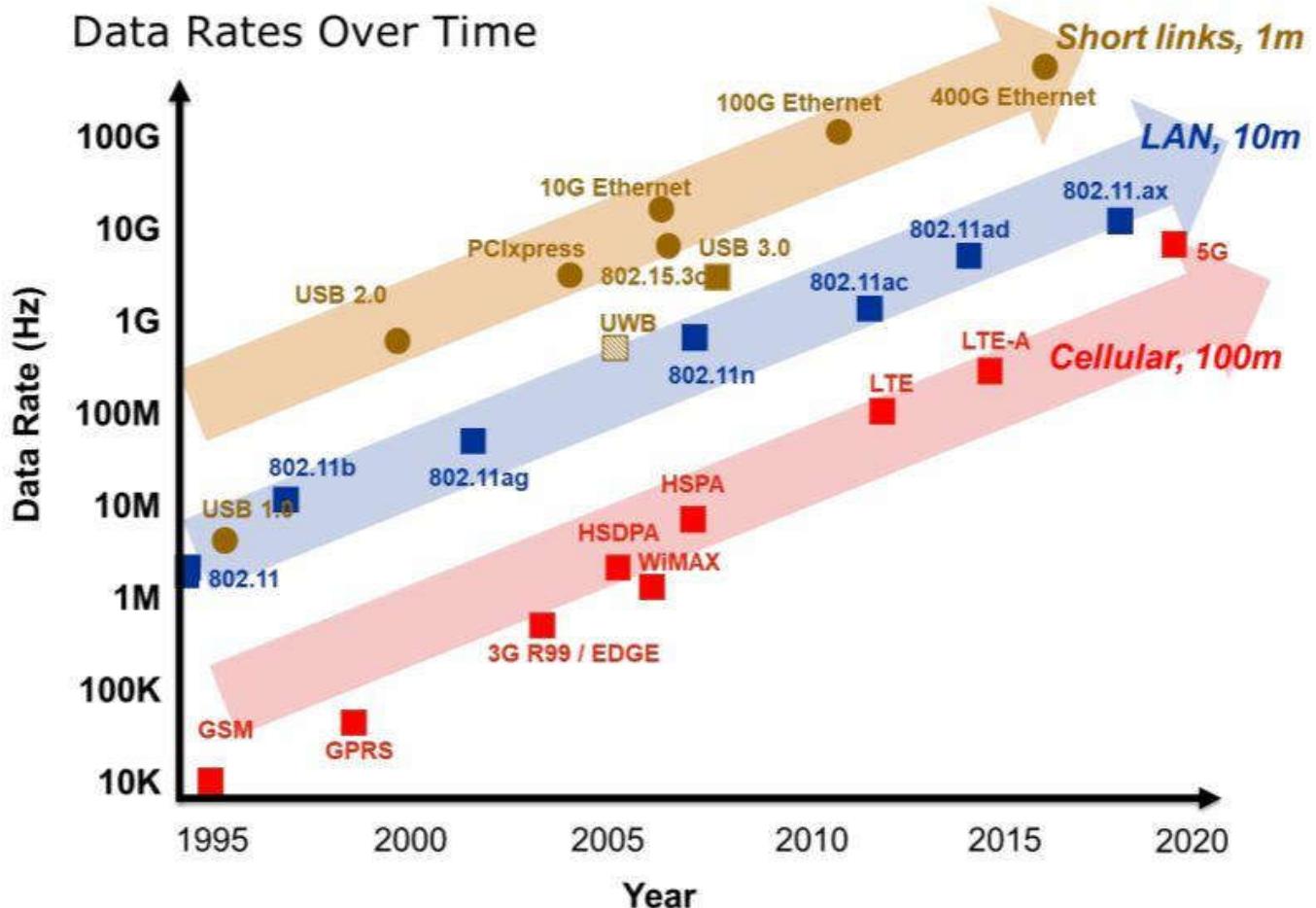


PCIe				SATA		
Generation	Transfer Rate	Throughput per Lane		Generation	Transfer Rate	Throughput
Gen1	2.5 Gb/s	x1: 250 MB/s	x4: 1 GB/s	Gen1	1.5 Gb/s	150 MB/s
Gen2	4.9 Gb/s	x1: 500 MB/s	x4: 2 GB/s	Gen2	3 Gb/s	300 MB/s
Gen3	7.9 Gb/s	x1: 984.6 MB/s	x4: 3.9 GB/s	Gen3	6 Gb/s	600 MB/s
Gen4	15.8 Gb/s	x1: 1,969 MB/s	x4: 7.8 GB/s			

[ATP, 2018]

Escala de Comunicação

- Interface de E/S precisa ter desempenho?



[MORRIS, 2019]

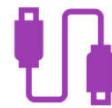
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Introdução



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Dispositivos de
E/S



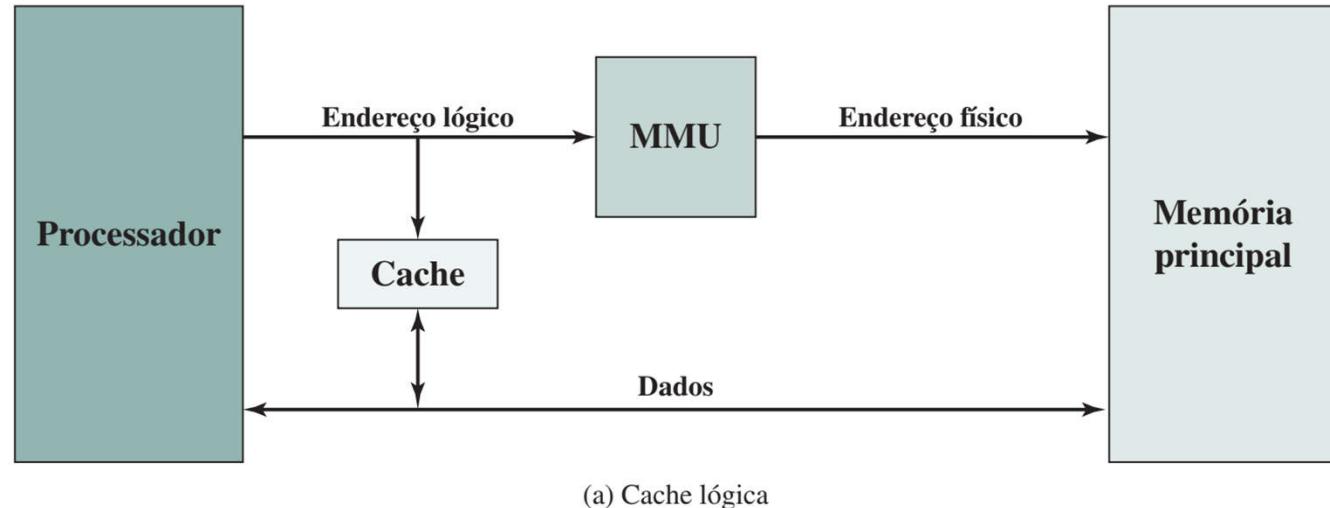
Armazenamento
de Dados



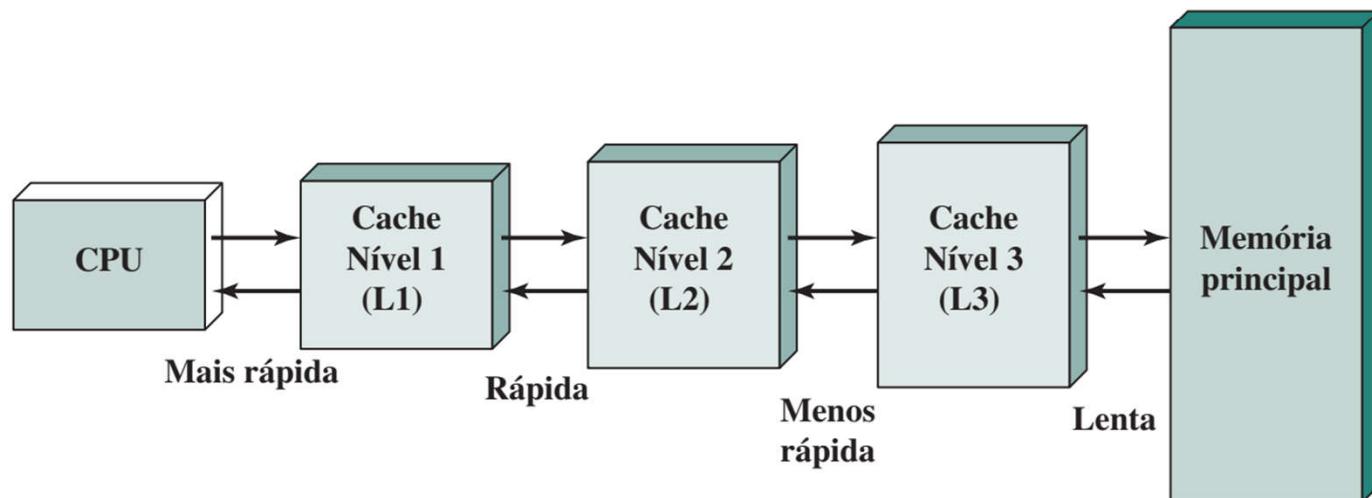
Processamento
da Dados

Memória (RAM e Cache)

- UNIDADE DE GERENCIAMENTO DE MEMÓRIA (MMU)
- NÍVEIS DE CACHE



(a) Cache lógica



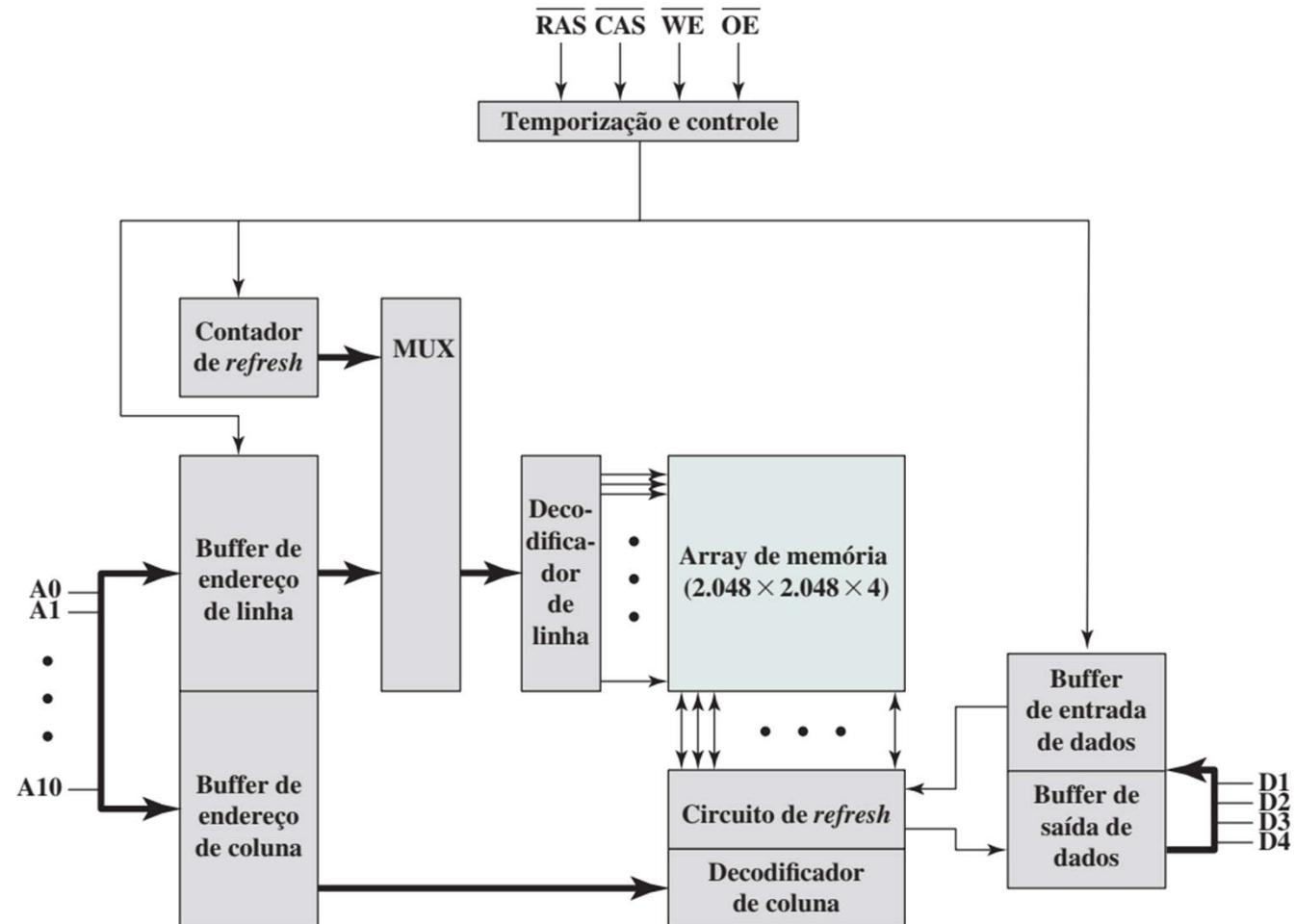
(b) Organização de cache de três níveis

[STALLINGS, 2010]

Memória (RAM)

- Como é feita a leitura e escrita na memória?
- Memória de 256KB
- Memória de Acesso Randômico Dinâmica (DRAM)

DRAM típica de 16 Mbits ($4 \text{ M} \times 4$).

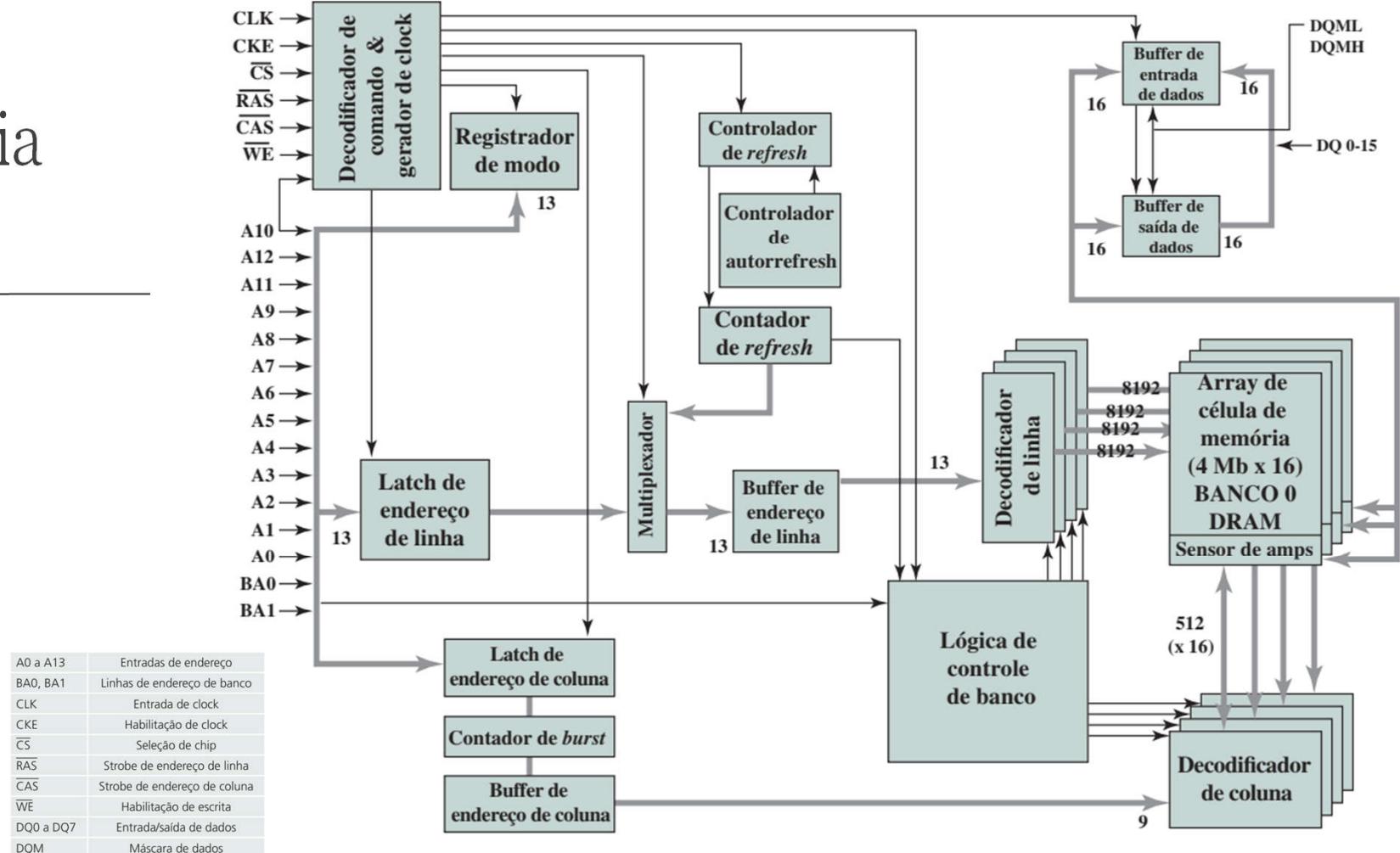


[STALLINGS, 2010]

Memória (RAM)

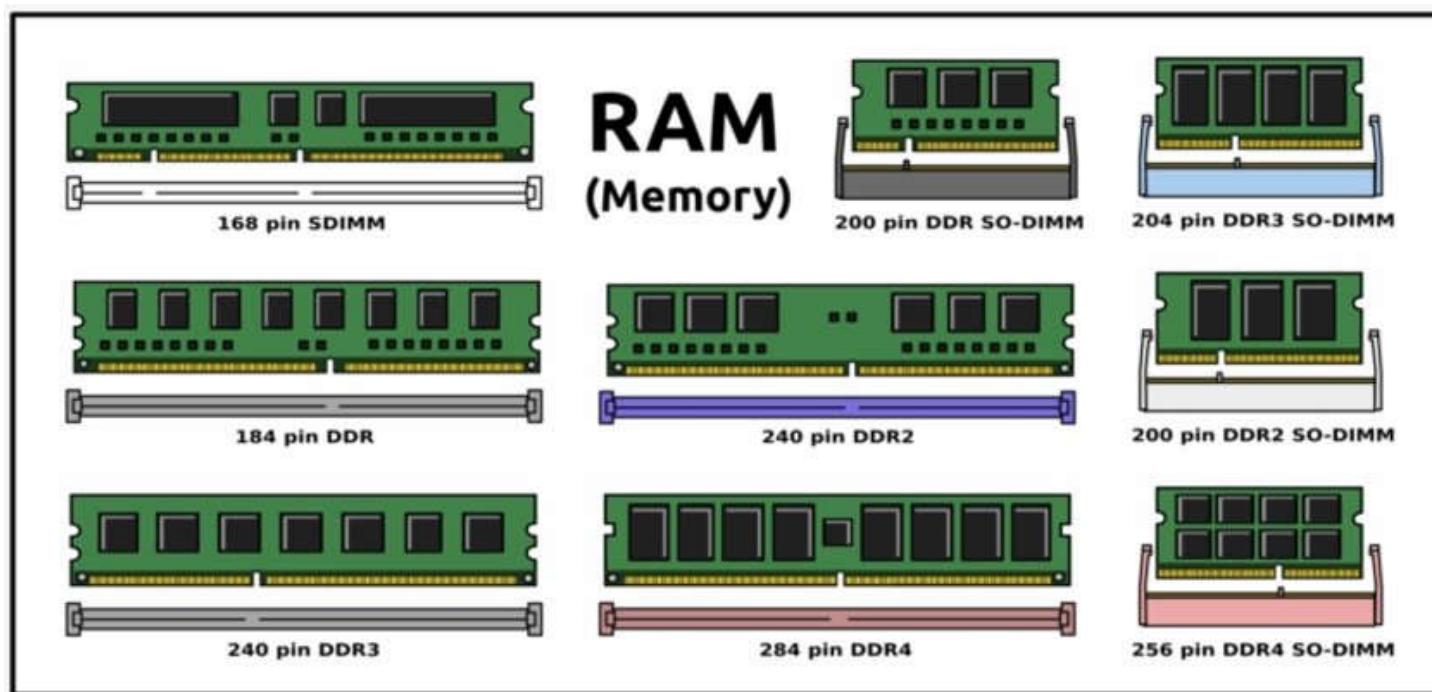
- Memória de Acesso Randômico Dinâmica Síncrona (SDRAM)

RAM dinâmica síncrona (SDRAM) de 256 Mb.



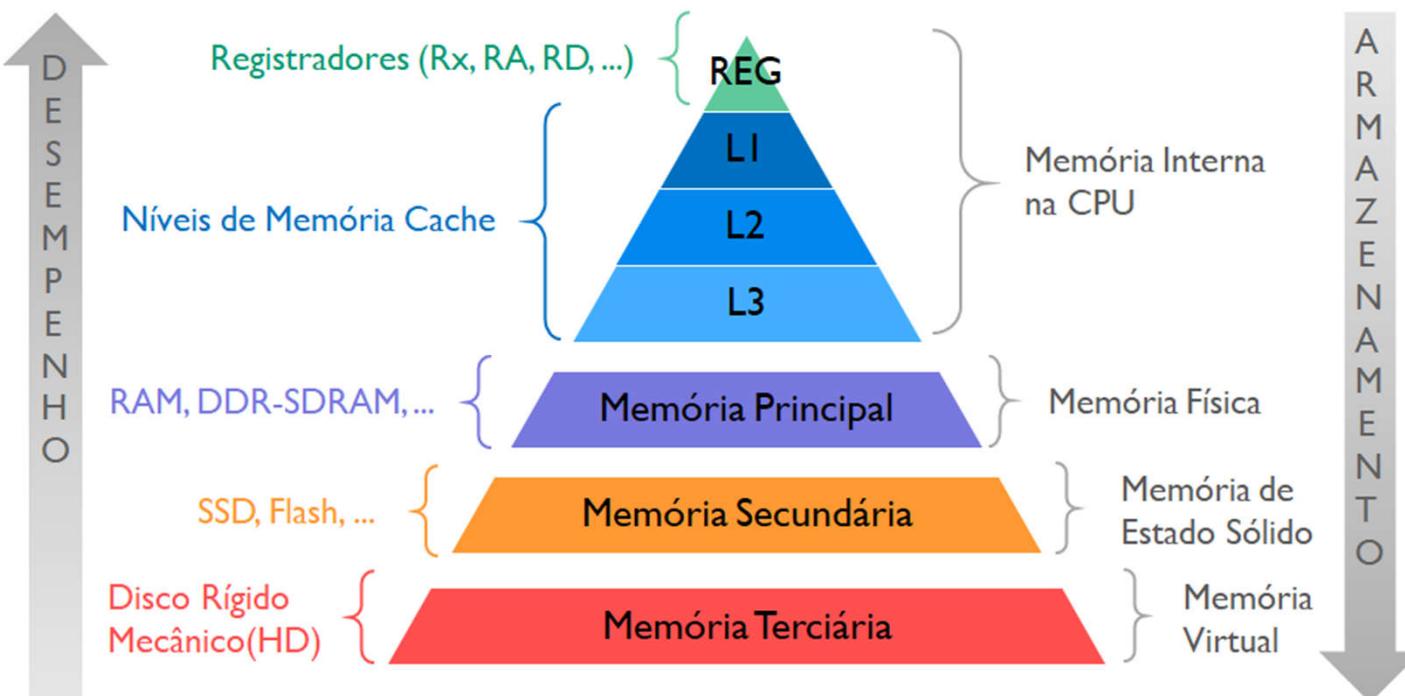
[STALLINGS, 2010]

RAM - Random Access Memory (Memória de Acesso Aleatório)



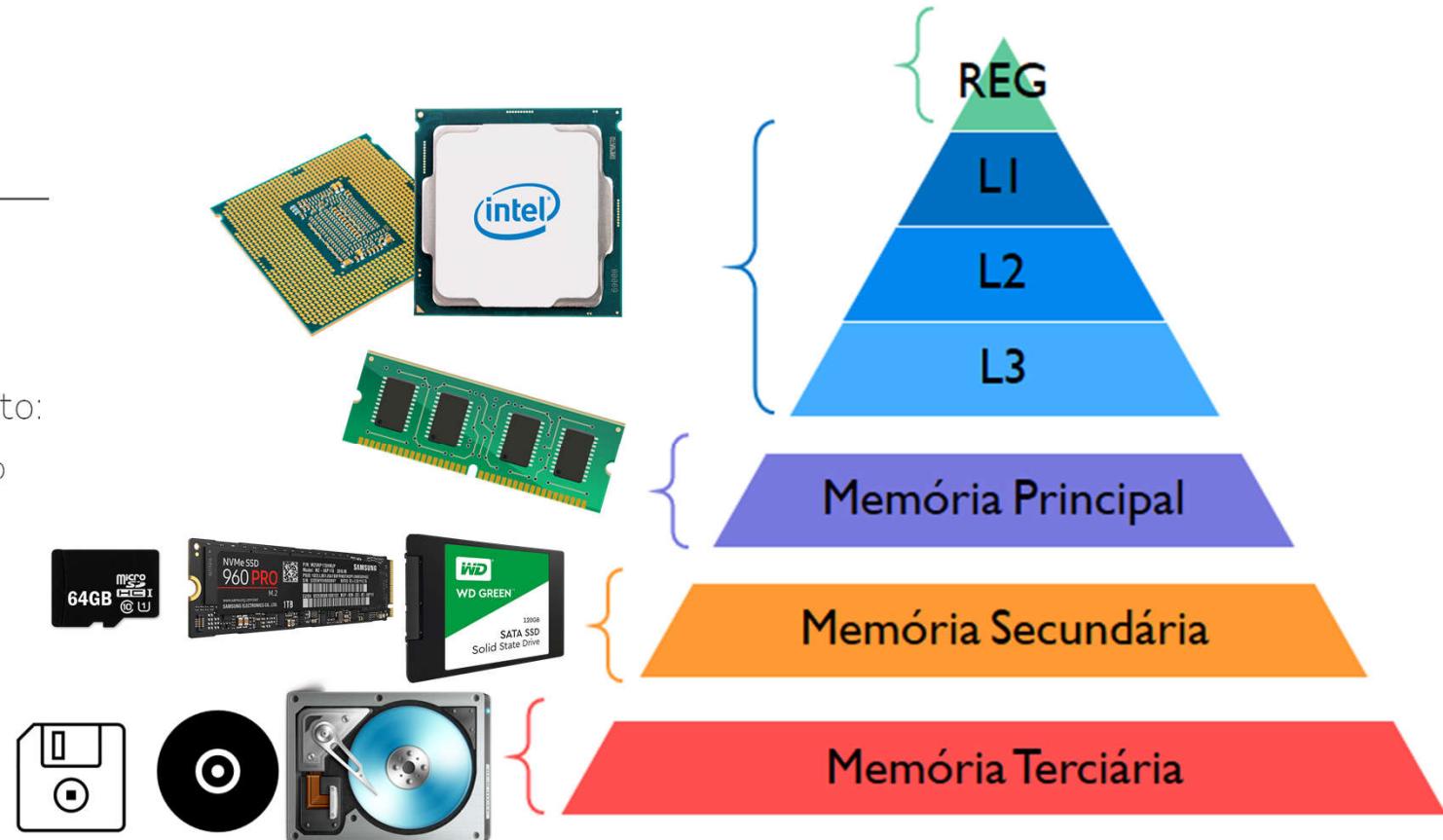
Hierarquia de Memória

- Você tem memória curta ou rápida?
- Temporária ou Permanente?



Hierarquia de Memória

- Você tem memória de elefante ou camudongo?
- Forma de armazenamento:
 - Eletromecânico ou estado sólido?

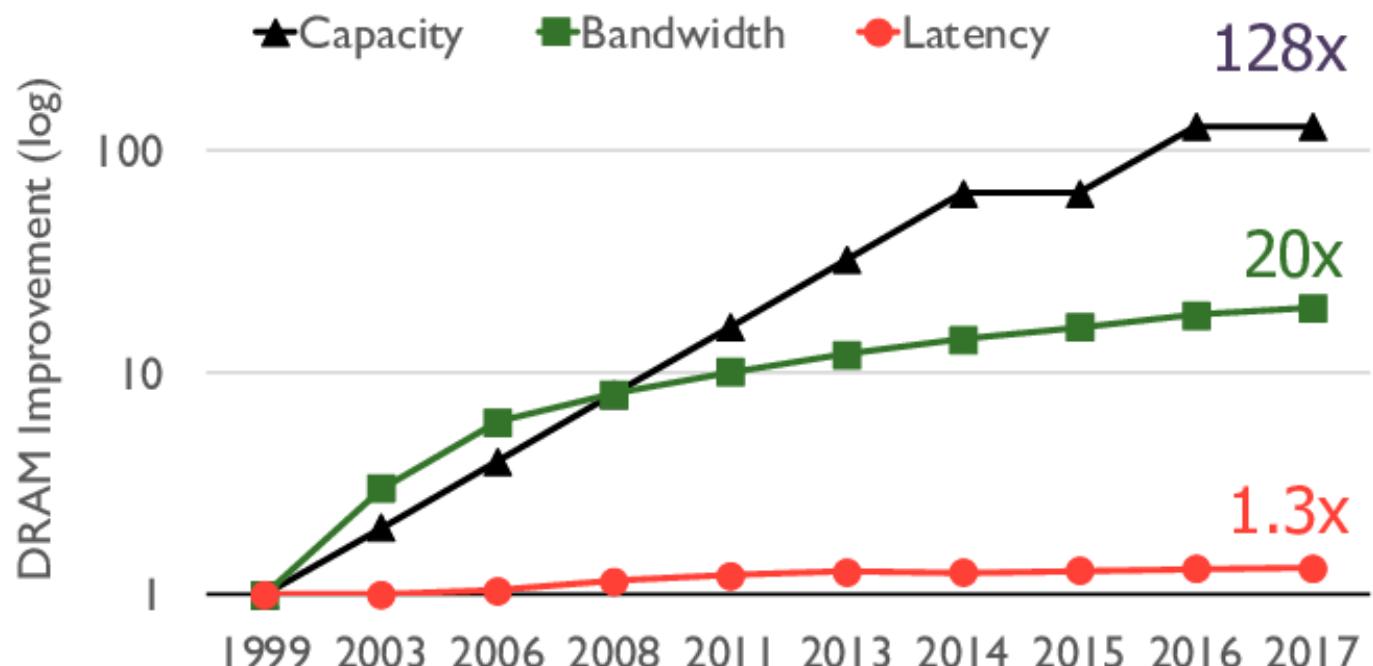


[HICLIPART, 2020]

Escala de Memória

- DRAM (Dynamic Random Access Memory)
- SDRAM (Synchronous Dynamic Random Access Memory)

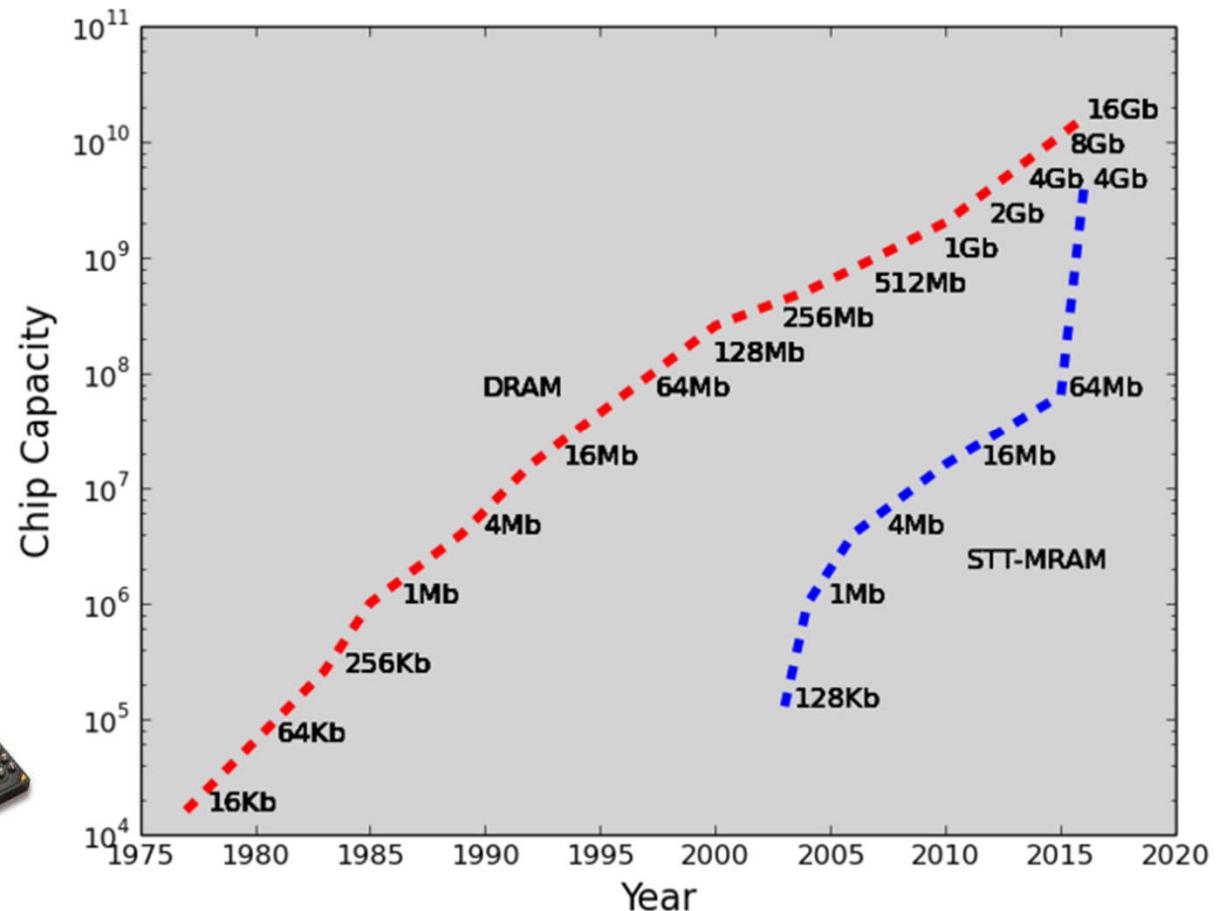
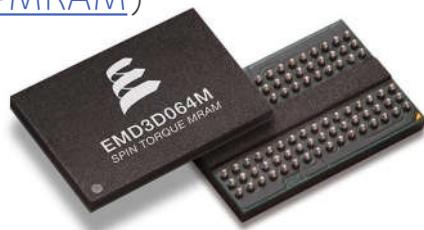
DRAM Capacity, Bandwidth & Latency



[Mutlu et al., 2020]

Linha do Tempo

- [The International Symposium on Memory Systems 2017](#) (MEMSYS)
- Spin-Transfer Torque Magnetic Random Access Memory ([STT-MRAM](#))

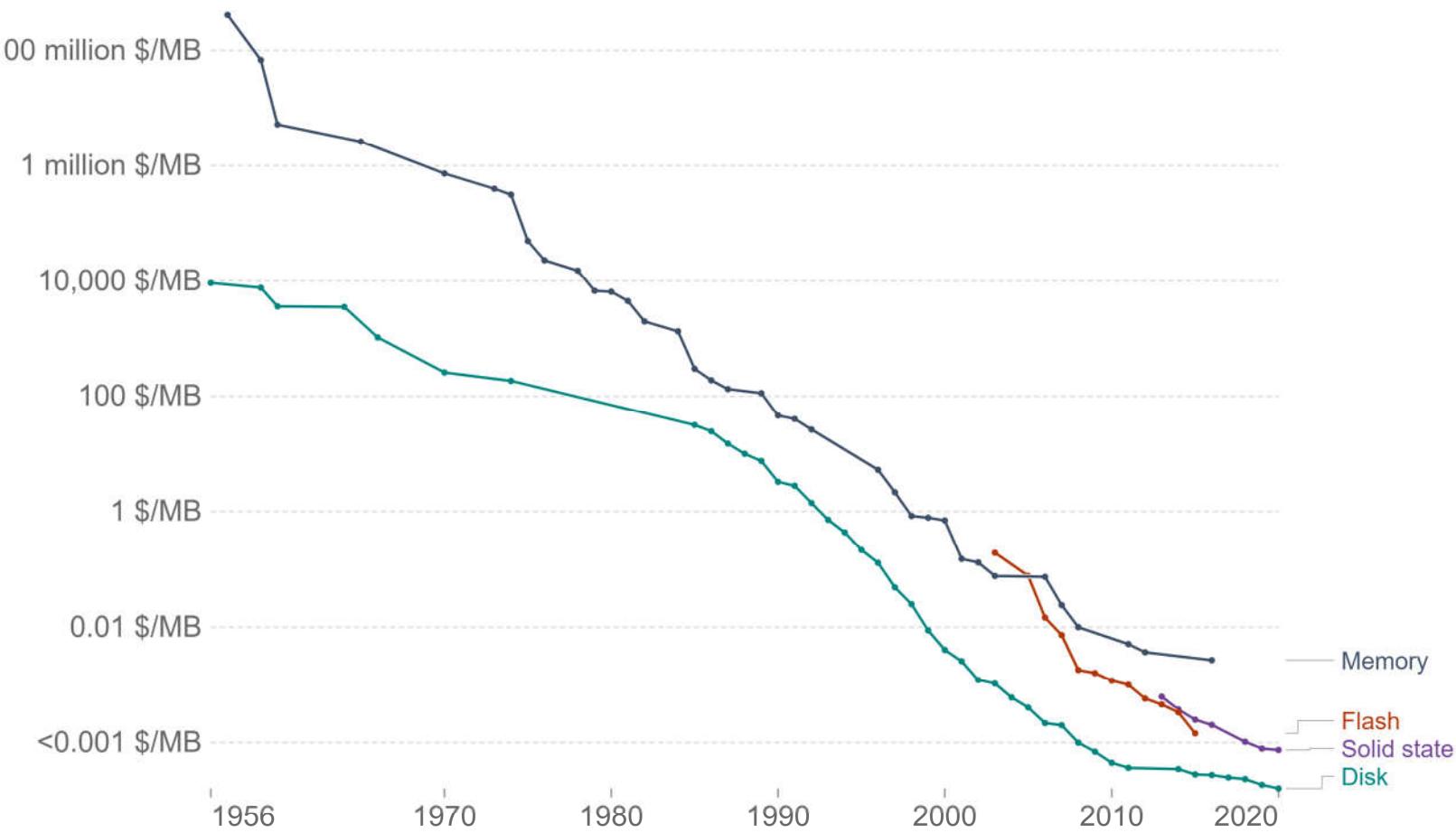


[ASIFUZZAMAN, 2017]

Historical cost of computer memory and storage

Measured in US dollars per megabyte.

Evolução da Memória



[Roser and Ritchie, 2022]

Source: John C. McCallum (2022)

Note: For each year the time series shows the cheapest historical price recorded until that year.

CC BY

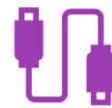
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E/S



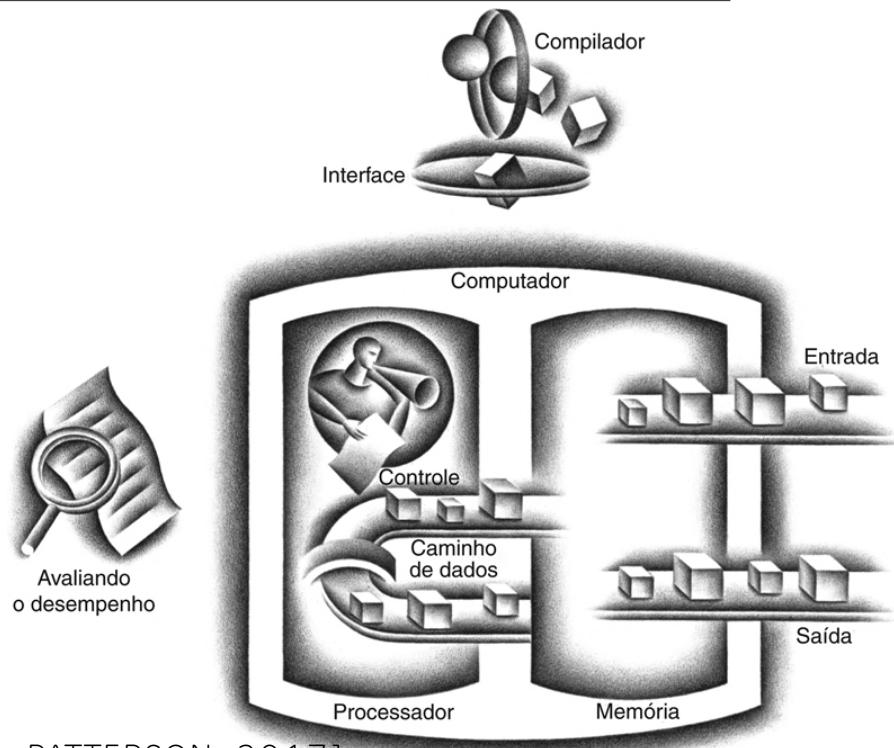
Armazenamento
de Dados



Processamento
da Dados

Processamento de Dados

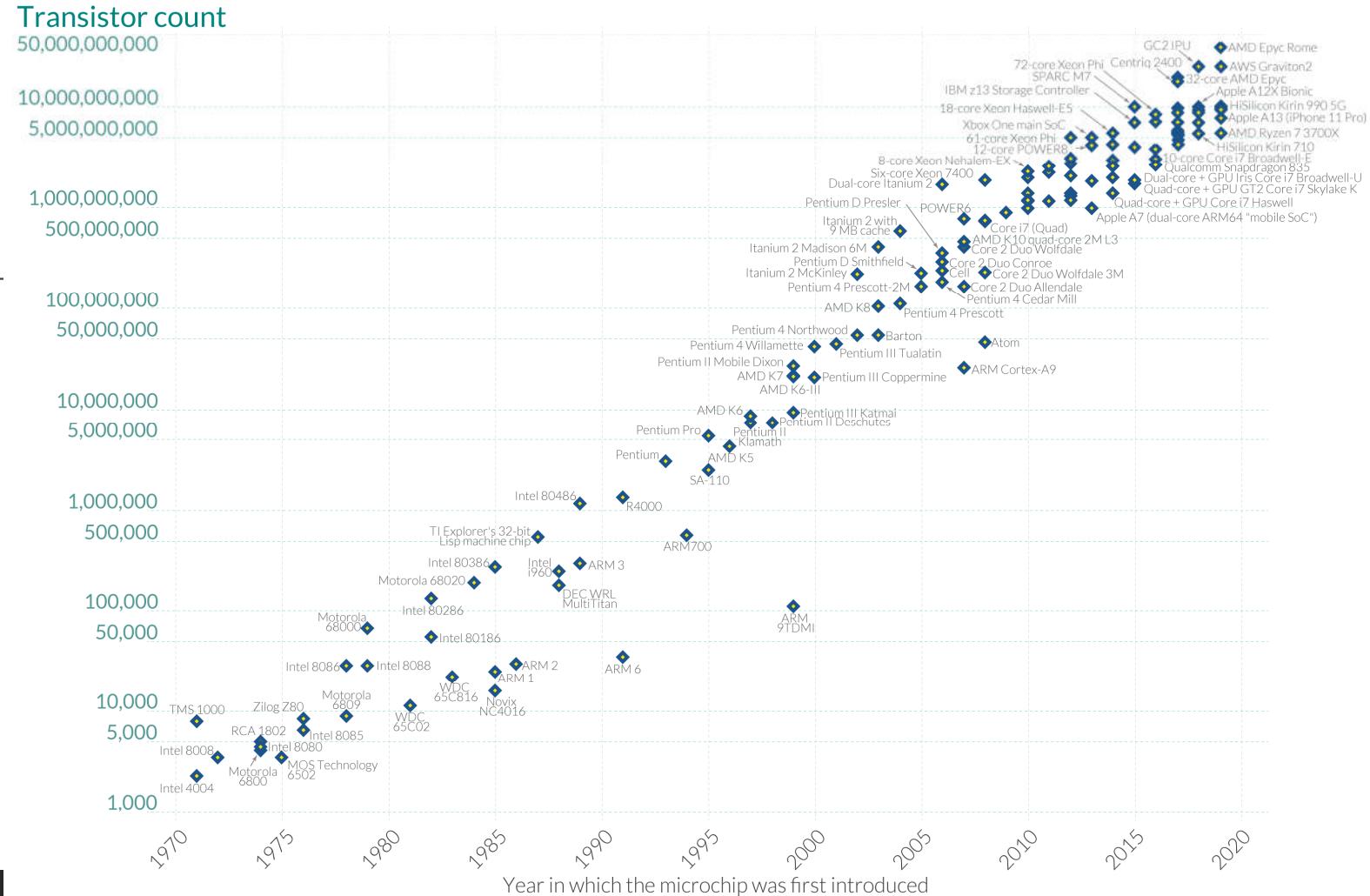
- Central Processor Unit (CPU) / Processador
 - Contém datapath e controle
 - Efetua operações matemáticas (Lógicas e Aritméticas)
 - Faz operações e comparações com números, ativa sinais de controle em diversos dispositivos, etc.
- Datapath / Bloco de Dados
 - Componente do processador que realiza operações matemáticas
- Controle / Bloco de Controle
 - Componente do processador que comanda o datapath, memória, e E/S
 - Responde aos comandos informados pelas instruções do programa



[HENNESSY e PATTERSON, 2017]

Moore's Law: The number of transistors on microchips has doubled every two years

Moore's law describes the empirical regularity that the number of transistors on integrated circuits doubles approximately every two years. This advancement is important for other aspects of technological progress in computing – such as processing speed or the price of computers.



Our World
in Data

Lei de Moore

- 1965 postulou uma duplicação a cada ano no número de componentes por circuito integrado
 - Em 1975, olhando para a próxima década, ele revisou a previsão para dobrar a cada dois anos, CAGR de 40%

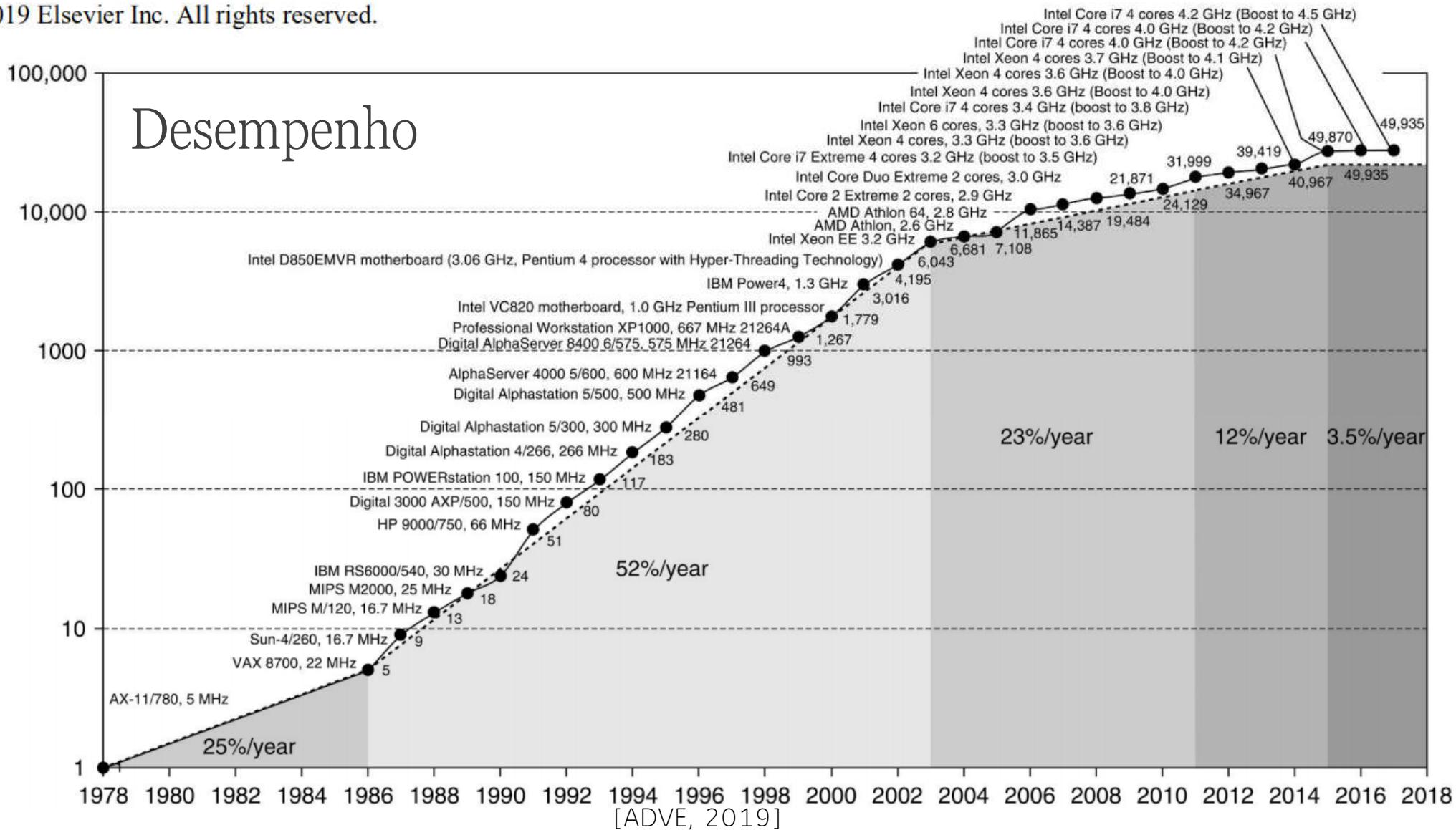
[WIKIPEDIA, 2020]

[Roser and Ritchie, 2022]

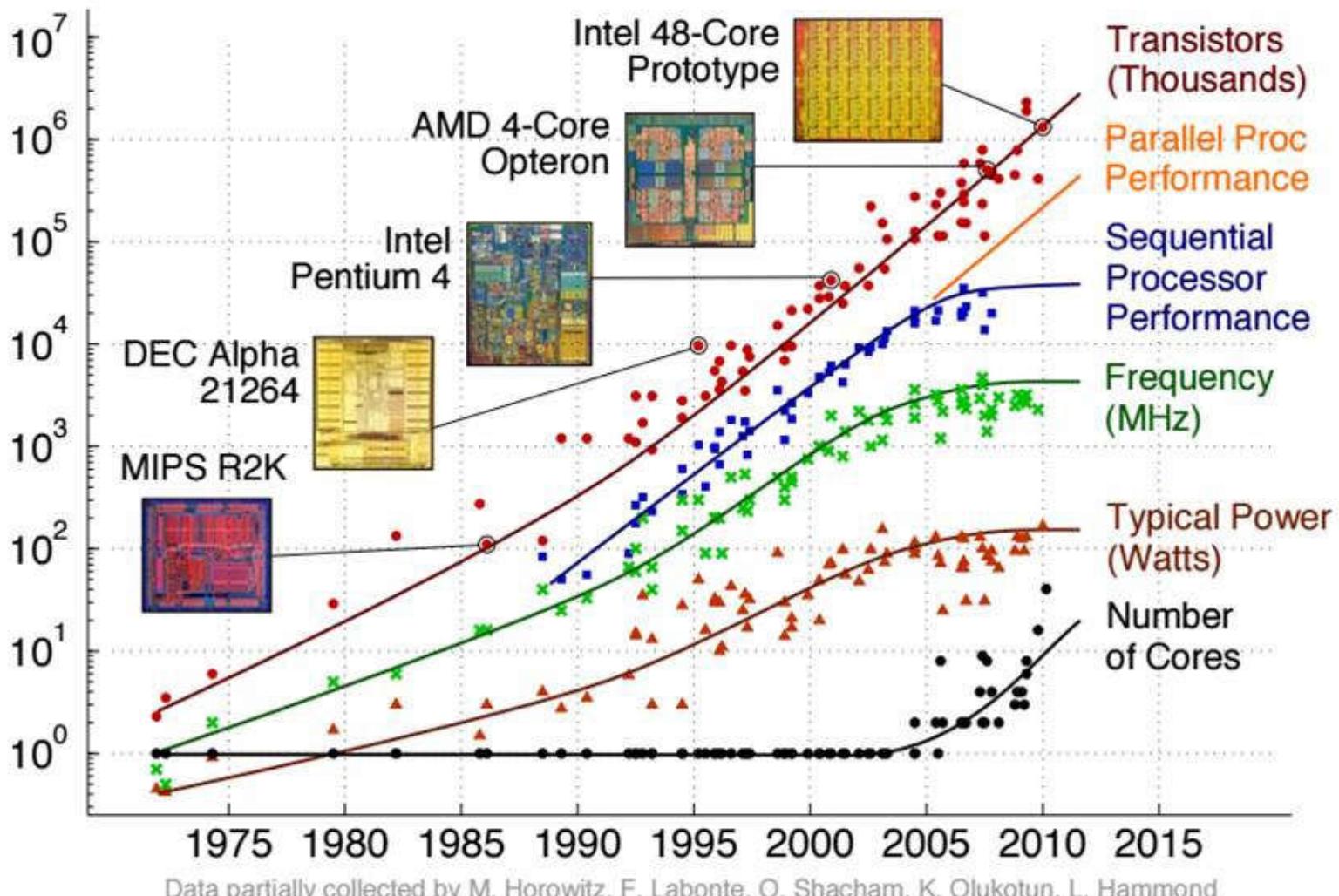
Data source: Wikipedia ([wikipedia.org/wiki/Transistor_count](https://en.wikipedia.org/wiki/Transistor_count))

[OurWorldInData.org](https://www.worldindata.org) – Research and data to make progress against the world's largest problems

Licensed under CC-BY by the authors Hannah Ritchie and Max Roser.



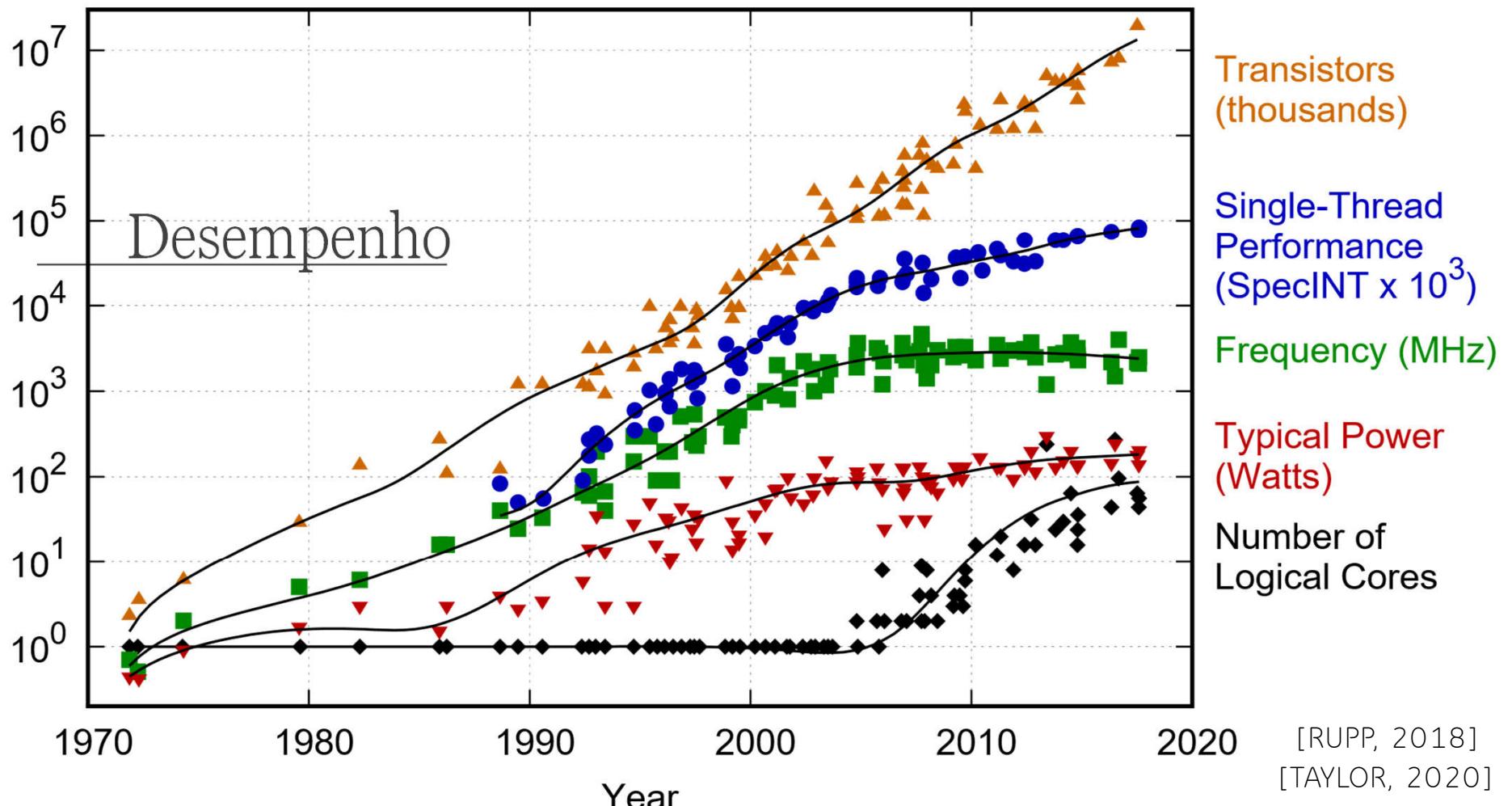
Desempenho



[ADVE, 2019]

UNEMAT

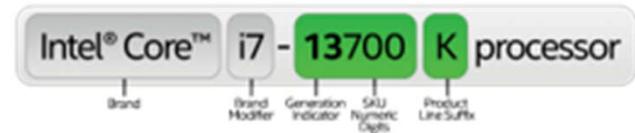
42 Years of Microprocessor Trend Data



[RUPP, 2018]
[TAYLOR, 2020]

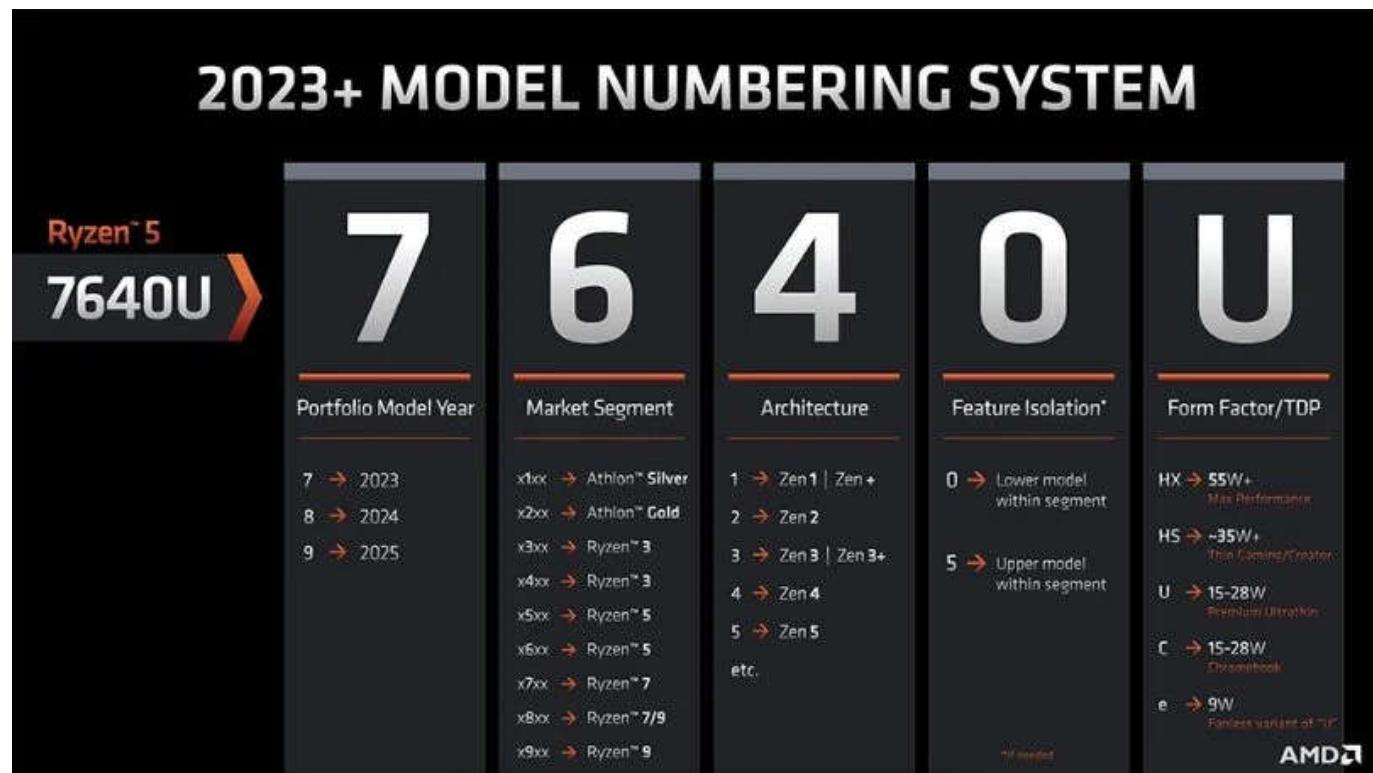
Original data up to the year 2010 collected and plotted by M. Horowitz, F. Labonte, O. Shacham, K. Olukotun, L. Hammond, and C. Batten
New plot and data collected for 2010-2017 by K. Rupp

Intel - Codificação dos modelos



Forma/Tipo de Função/Segmento	Sufixo	Otimizado/Projetado para
Desktop	K	Alto desempenho, desbloqueado
	F	Requer gráficos dedicados
	S	Edição especial
	T	Estilo de vida otimizado pela energia
	X/XE	Desempenho mais alto, desbloqueado
Dispositivo móvel	HX	Desempenho mais alto, todas as SKUs desbloqueadas
	HK	Alto desempenho, desbloqueado
	H	Alto desempenho
	P	Desempenho do fino e leve
	U	Eficiência no consumo de energia
	Y	Consumo de energia extremamente baixo
	G1-G7	Nível da placa gráfica

AMD - Codificação dos modelos

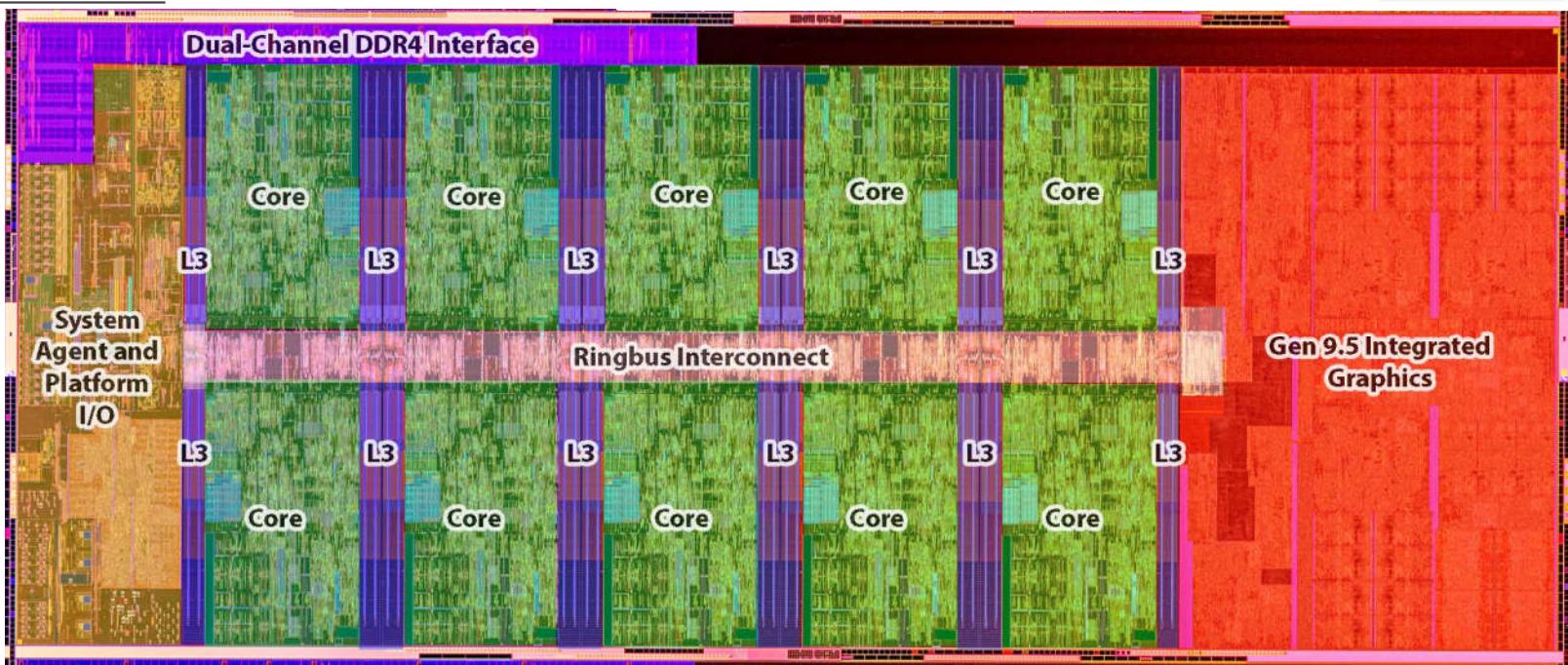


[GIANNOTTI, 2022]

Arquitetura

[TECHPOWERUP, 2020]

- Die
- Intel core i9
 - 10850k



	Sandy Bridge	Haswell	SkyLake
Out-of-order Window	168	192	224
In-flight Loads	64	72	72
In-flight Stores	36	42	56
Scheduler Entries	54	60	97
Integer Register File	160	168	180
FP Register File	144	168	168
Allocation Queue	28/thread	56	64/thread

Arquitetura AMD

- Arquitetura Zen
 - Zen, Zen2 e Zen3

“ZEN”/“ZEN+”

- Up to 4.35GHz max boost⁴
- +52% IPC¹
- 4-core complex
- 8MB L3 per complex
- SMT enabled
- New boost algorithms
- 14nm/12nm

“ZEN 2”

- Up to 4.7GHz max boost
- +15% IPC²
- 4-core complex
- 16MB L3 per complex
- Chiplet design
- FP-256
- 7nm

“ZEN 3”

- Up to 4.9GHz max boost
- +19% IPC³
- New 8-core complex
- New 32MB L3 cache topology
- 7nm

The diagram illustrates the evolution of AMD's Zen architecture from 2017 to 2021. It features a timeline at the bottom with markers for 2017, 2019, and 2021. In 2017, the "ZEN" and "ZEN+" processors are shown. In 2019, the "ZEN 2" layout is introduced, featuring a chiplet design with four cores and two 16MB L3 cache blocks. In 2021, the "ZEN 3" layout is shown, featuring an 8-core complex and a new 32MB L3 cache topology. The diagram also includes a close-up of a single AMD Ryzen 5000 Series processor die.

AMD
WHERE GAMING BEGINS
AMD RYZEN™ 5000 SERIES

<https://www.amd.com/pt/technologies/zen-core-3>

Processador Intel

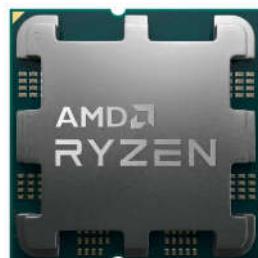
- Intel core i9

[WIKIPEDIA, 2020-a]



Model number	Spec number	Cores (threads)	Frequency	Turbo Boost all-core/2.0 (max. 3.0)	L2 cache	L3 cache	TDP	Socket	I/O bus	Memory	Release date	Part number(s)	Release price (USD)
Core i9-7900X	SR3L2 (U0)	10 (20)	3.3 GHz	4.0 ^[6] /4.3 GHz 4.5 GHz	10 x 1024 KiB	13.75 MiB	140 W	LGA 2066	DMI 3.0	4 x DDR4-2666	June 2017	BX80673I97900X BXC80673I97900X CD8067303286804	\$989
Core i9-7920X	SR3NG (U0)	12 (24)	2.9 GHz	3.8/4.3 GHz 4.4 GHz	12 x 1024 KiB	16.50 MiB	140 W	LGA 2066	DMI 3.0	4 x DDR4-2666	August 2017	BX80673I97920X CD8067303753300	\$1199
Core i9-7940X	SR3RQ (U0)	14 (28)	3.1 GHz	3.8/4.3 GHz 4.4 GHz	14 x 1024 KiB	19.25 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	September 2017	BX80673I97940X BXC80673I97940X CD8067303734701	\$1399
Core i9-7960X	SR3RR (U0)	16 (32)	2.8 GHz	3.6/4.2 GHz 4.4 GHz	16 x 1024 KiB	22.00 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	September 2017	BX80673I97960X BXC80673I97960X CD8067303734802	\$1699
Core i9-7980XE	SR3RS (U0)	18 (36)	2.6 GHz	3.4/4.2 GHz 4.4 GHz	18 x 1024 KiB	24.75 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	September 2017	BX80673I97980X CD8067303734902	\$1999
Core i9-9820X	SREZ8 (M0)	10 (20)	3.3 GHz	4.0/4.1 GHz 4.2 GHz	10 x 1024 KiB	16.50 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	Q4 2018	BX80673I99820X CD8067304126901	\$889
Core i9-9900X	SREZ7 (M0)	10 (20)	3.5 GHz	4.1/4.4 GHz 4.5 GHz	10 x 1024 KiB	19.25 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	Q4 2018	BX80673I99900X CD8067304126200	\$989
Core i9-9920X	SREZ6 (M0)	12 (24)	3.5 GHz	4.2/4.4 GHz 4.5 GHz	12 x 1024 KiB	19.25 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	Q4 2018	BX80673I99920X CD8067304126300	\$1189
Core i9-9940X	SREZ5 (M0)	14 (28)	3.3 GHz	4.1/4.4 GHz 4.5 GHz	14 x 1024 KiB	19.25 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	Q4 2018	BX80673I99940X CD8067304175600	\$1387
Core i9-9960X	SREZ4 (M0)	16 (32)	3.1 GHz	4.0/4.4 GHz 4.5 GHz	16 x 1024 KiB	22.00 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	Q4 2018	BX80673I99960X CD8067304126500	\$1684
Core i9-9980XE	SREZ3 (M0)	18 (36)	3 GHz	3.8/4.4 GHz 4.5 GHz	18 x 1024 KiB	24.75 MiB	165 W	LGA 2066	DMI 3.0	4 x DDR4-2666	Q4 2018	BX80673I99980X CD8067304126600	\$1979
Core i9-9990XE	SREZA (M0)	14 (28)	4 GHz	5.0/5.0 GHz 5.1 GHz	14 x 1024 KiB	19.25 MiB	255 W	LGA 2066	DMI 3.0	4 x DDR4-2666	January 2019	auctions for OEMs ^[7]	

Processadores



Componentes	Ryzen Threadripper Pro 5995WX - Zen3	Ryzen 9 7950X - Zen4	i9 13900K	i7 13700
Frequência Turbo Max.	4.5 (GHz)	5.7 (GHz)	5.8 (GHz)	5.2 (GHz)
Cores	64	16	(p-cores + e-cores): 24 (8p+16e)	(p-cores + e-cores): 16 (8p+8e)
Threads	128	32	32	24
RAM	DDR4 3200	DDR5 6400	DDR5 5600	DDR5 5600
Cache (L3)	256MB	64MB	36MB	30MB
Cache (L2)	32MB	16MB	32MB	24MB
Potência Turbo Máx.	280 W	170 W	253 W	219 W
Tecnologia Fab.	7 nm	5 nm	7nm	7nm
Preço	R\$ 39.999,99	R\$ 4.399,99	R\$ 6.249,96	R\$ 4.956,90

Escala de Transistor

• Quem é TSMC?

- Taiwan Semiconductor Manufacturing Company (TSMC)

• TSMC investe 24B em pesquisa em 2019, 4 a mais que a intel

1

Home > Mercado
Quem é a TSMC, a desconhecida de Taiwan que está roubando o trono da Intel?
Por Rafael Rodrigues da Silva | 29 de Novembro de 2018 às 09h43

[DA SILVA, 2018]



[ADRENALINE, 2020]

Futuros chips de AMD, Intel e Nvidia em 5nm já estariam reservados para produção pela TSMC

Processadores da arquitetura Zen4 e GPUs RDNA3, Xe e Hopper já teriam suas fabricações reservadas para os anos de 2021 e 2022

POR PEDRO HENRIQUE | 12/05/2020 20:05 | 56 | REPORTAR ERRO

Plano de investimento de 5nm da TSMC (5nm e 5nm+)

Produção em massa (2020)

- Apple: A14/A14X;
- Huawei HiSilicon: Kirin 1000 e chips para redes

Produção em massa (2021-2022)

- AMD: CPUs da microarquitetura Zen4 e GPUs Radeon RDNA3
- Broadcom: Chips para redes de alta velocidade
- Qualcomm: Snapdragon 875 e X60, além de outros modens 5G
- Nvidia: GPUs da arquitetura Hopper
- Mediatek: SoCs da série Dimensity 2000
- Intel: GPUs da arquitetura Xe ou FPGA
- Apple: A15 Bionic
- Huawei HiSilicon: Kirin 1100, além de processadores focados em AI e servidores

[HENRIQUE, 2020]

Only 2 Foundries Are At the Leading Edge Node

Key
Year in Production
of Companies
Node



Arm and TSMC Demonstrate Industry's First 7nm Arm-based CoWoS® Chiplets for High-Performance Computing

September 26, 2019
Hsinchu, Taiwan R.O.C., September 26, 2019 - Arm and TSMC, the High-Performance Computing (HPC) industry leaders, today announced an industry-first 7nm silicon-proven chiplet system based on multiple Arm® cores and leveraging TSMC's Chip-on-Wafer-on-Substrate (CoWoS®) advanced packaging solution. This single proof-of-concept chiplet system successfully demonstrates the key technologies for building an HPC System-On-Chip (SoC) with Arm-based cores operating

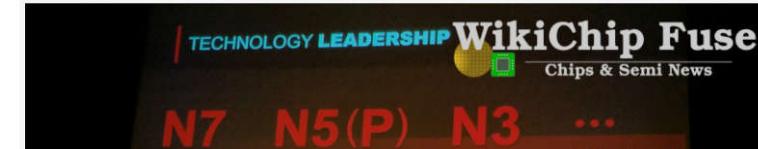
[ARM, 2019]

HOME MAIN SITE ARCHITECTURES SUPERCOMPUTERS 14 NM 12NM 10NM 7NM 5NM

Foundries IEDM 2019 ISSCC 2020 Process Technologies

TSMC Details 5 nm

March 21, 2020 | David Schor | 4 Comments | 5 nm, 7 nm, EUV, NS, NSP, TSMC

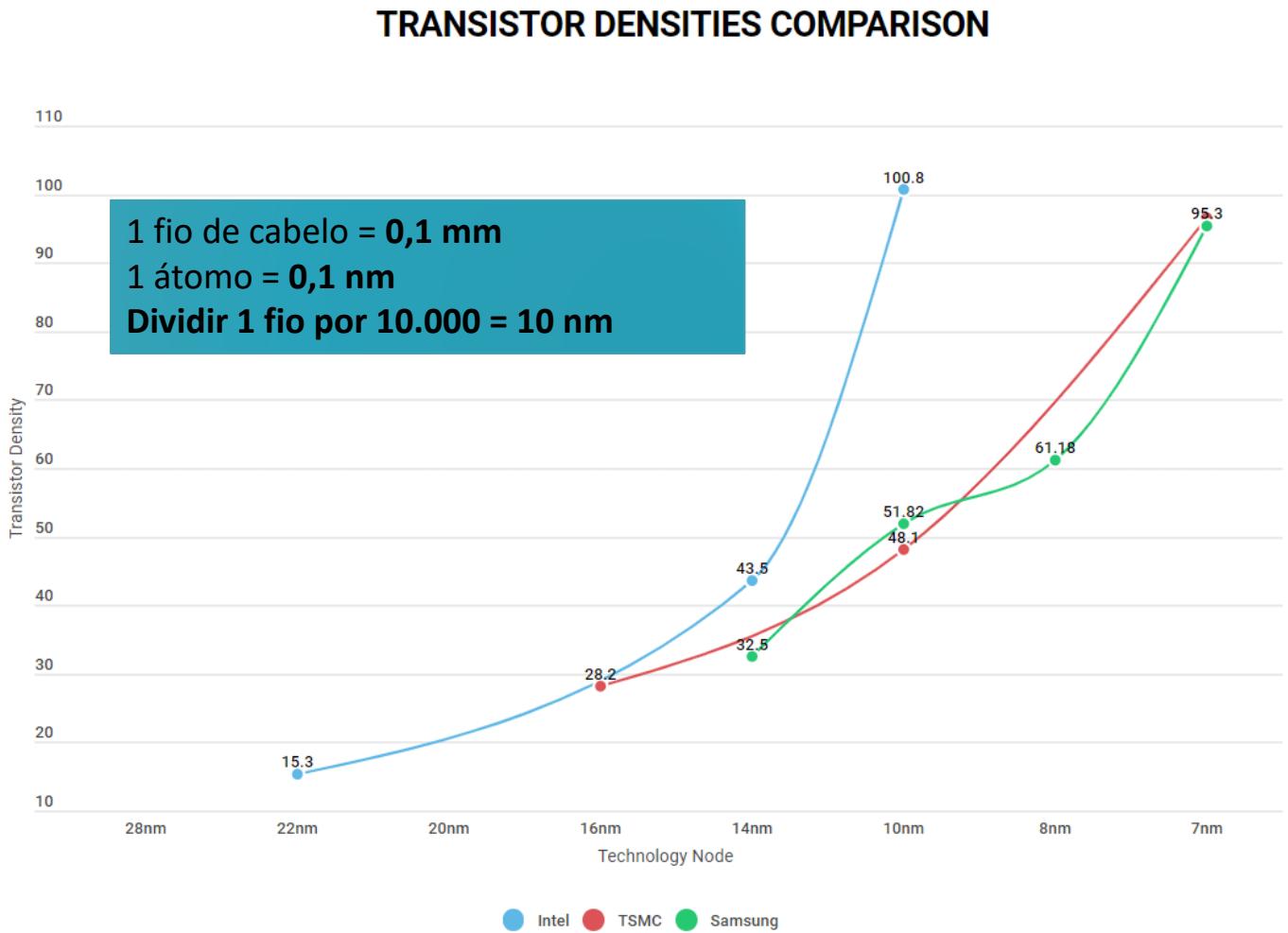


UNE MAT

Escala de Transistor

- E o mercado atual?
- Quem é TSMC?

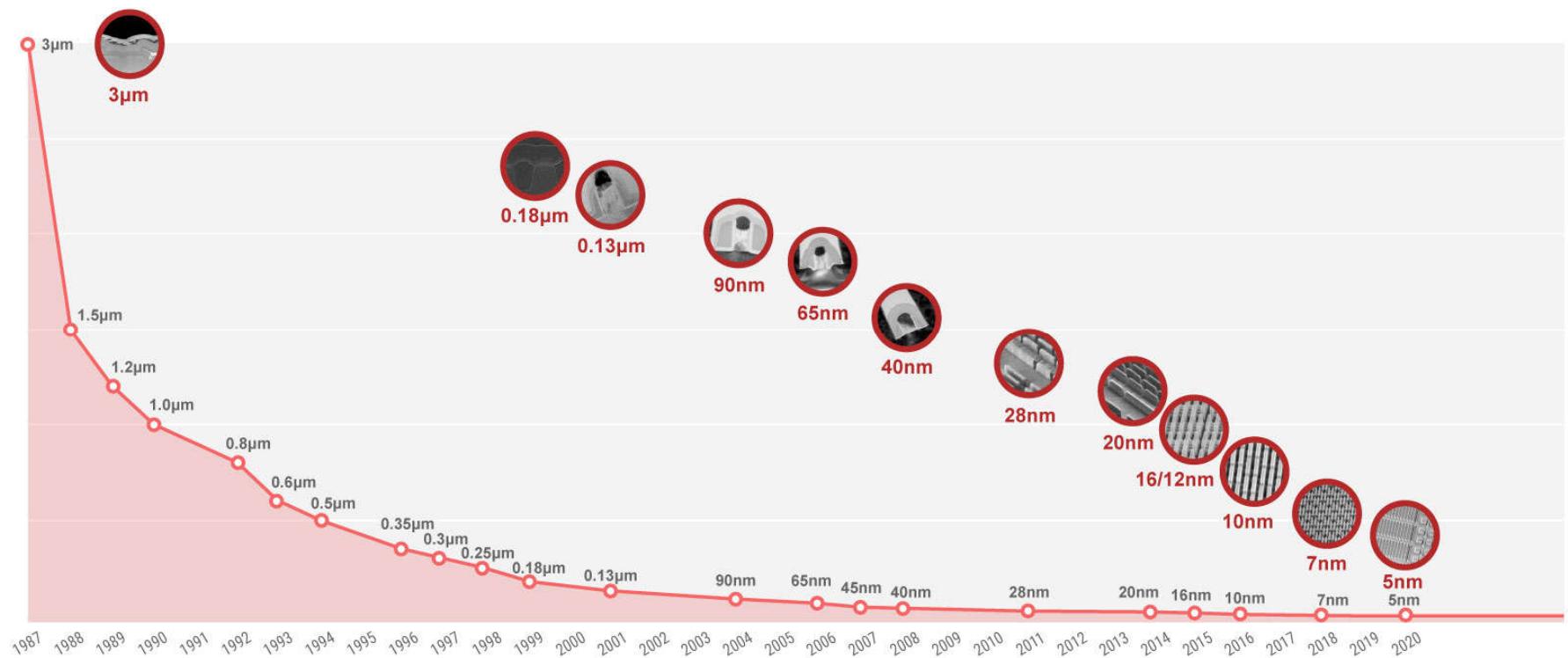
Rank	Process Name	Approximate Transistor Density (MTr/mm ²)
#1	TSMC's 5nm EUV	171.3
#2	TSMC's 7nm+ EUV	115.8
#4	Intel's 10nm	100.8*
#5	TSMC's 7nm (Mobile)	96.5
#6	Samsung's 7nm EUV	95.3



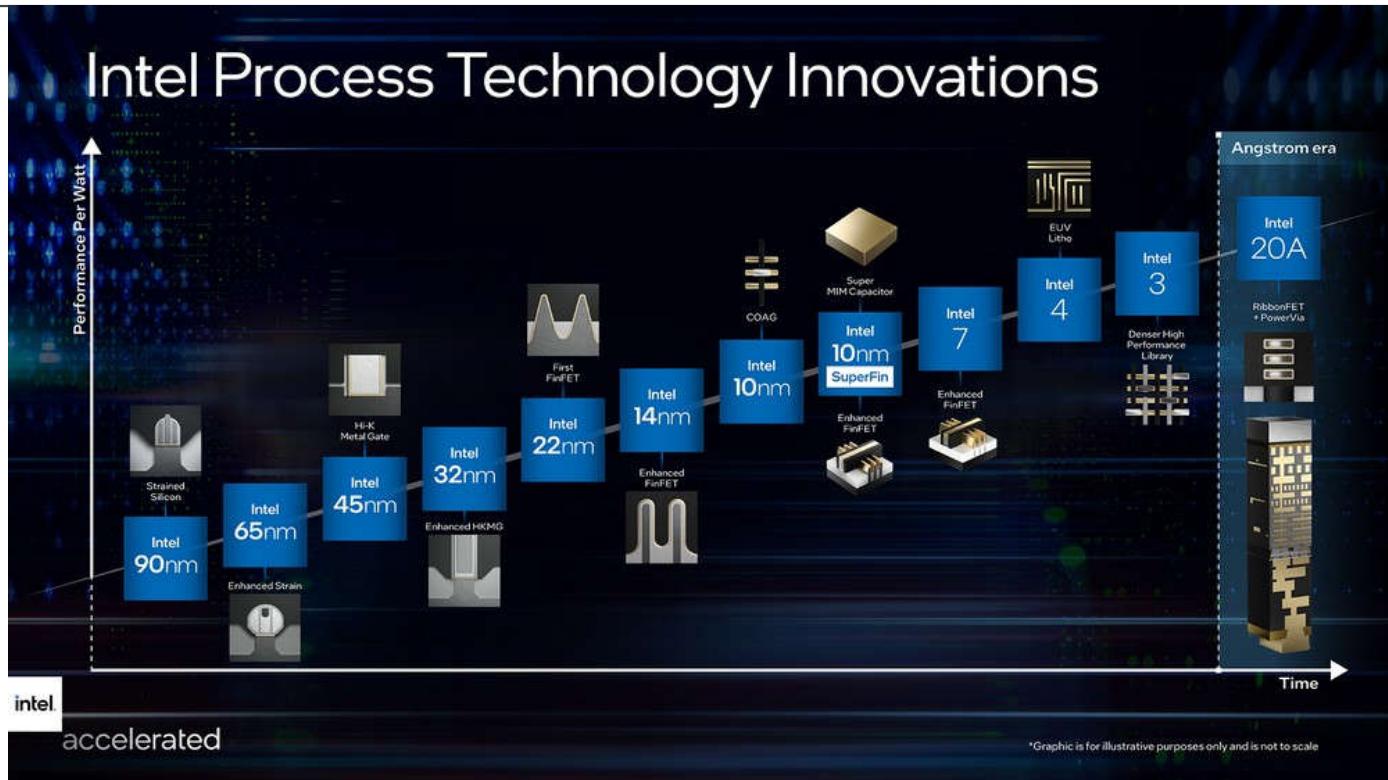
[KUMAWAT, 2019]

UNEMAT

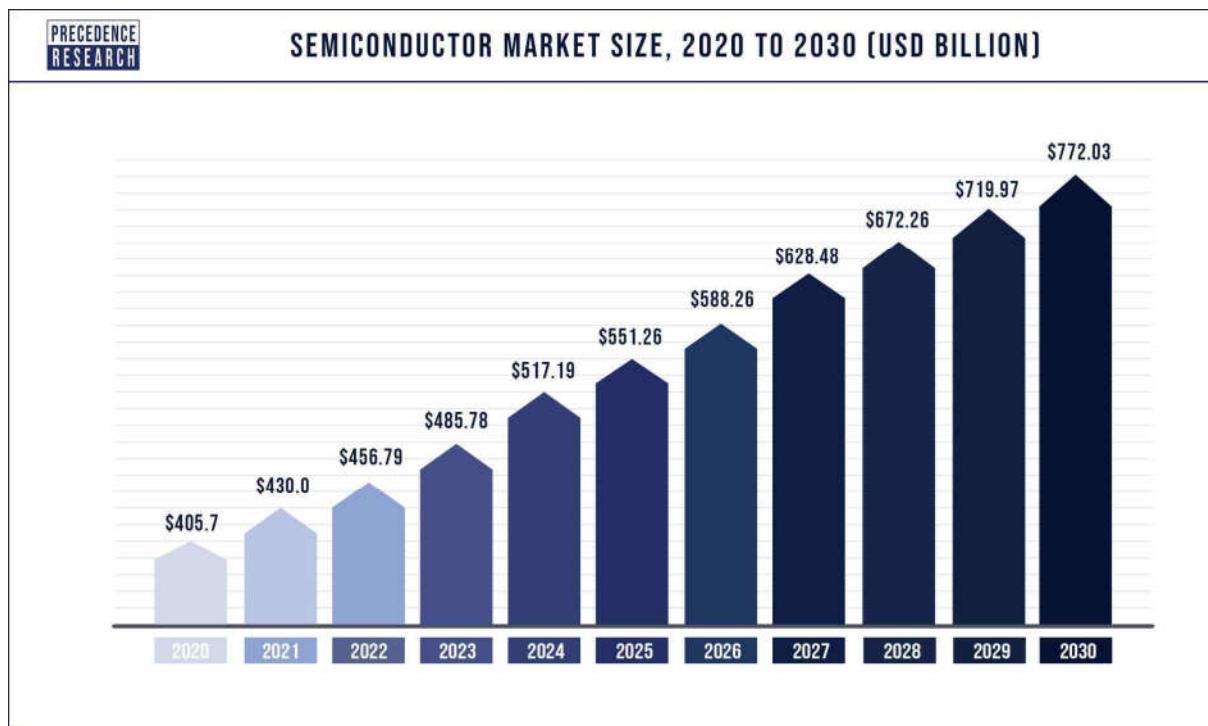
Escala de Transistor - TSMC



Escala de Transistor - Intel



Mercado de Semicondutores

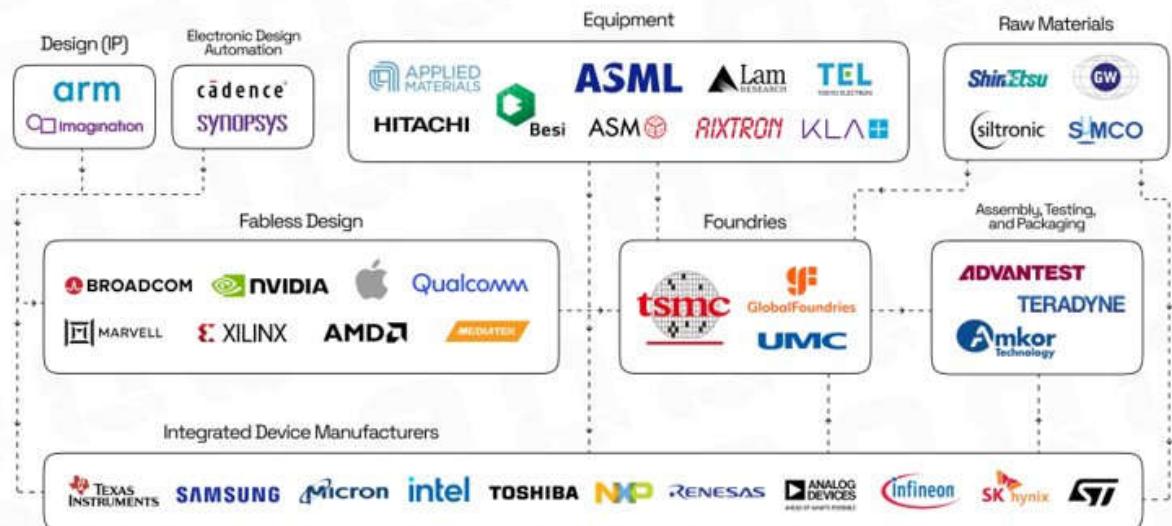


[Precedence Research, 2022]

EcoSistema dos Semicondutores

The Semiconductor Value Chain

Created by Quartr



Note: The exact flows might differ between companies (subsidiaries, hybrid business models, etc) | Created by Quartr_App

Advanced RISC Machine (ARM)

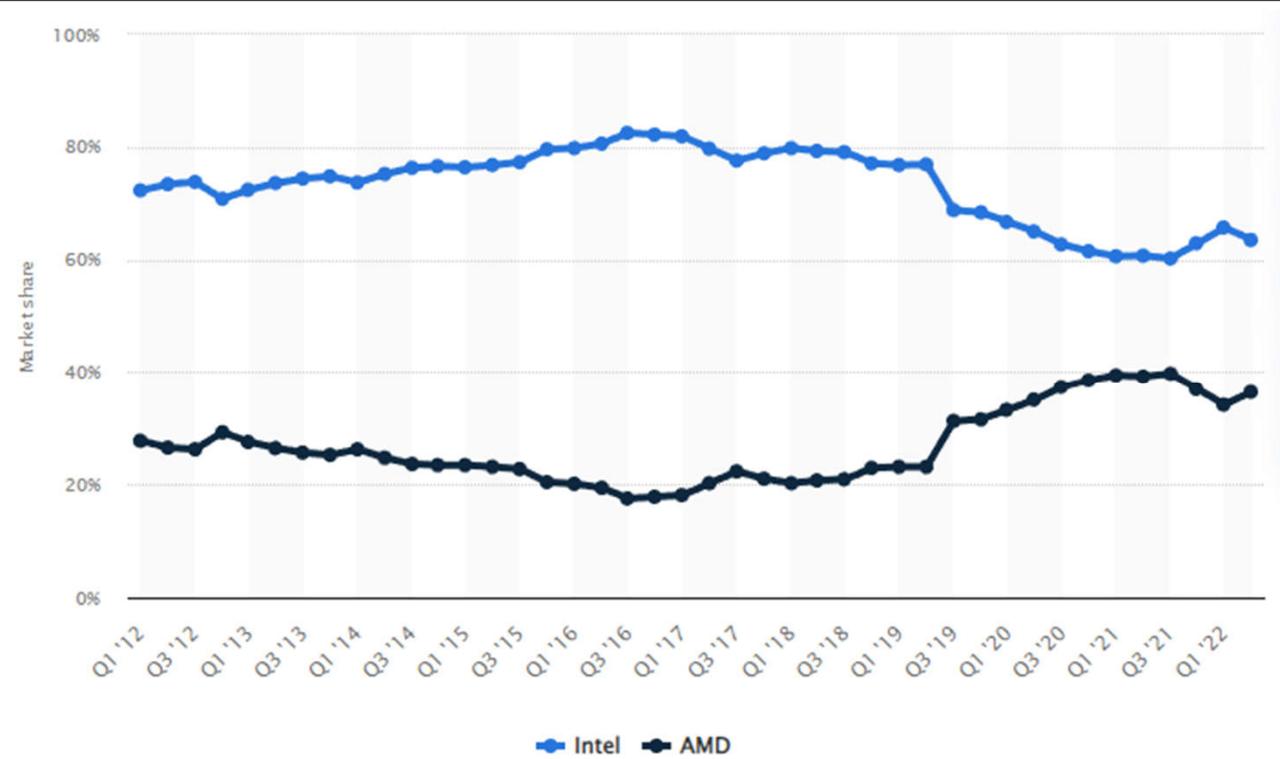
- Apple, Nvidia, Qualcomm, MediaTek, AMD, Samsung, Texas Instruments, Broadcom

V-T-E		Application ARM-based chips	
		ARM Holdings · ARM architecture · List of ARM microarchitectures · List of applications of ARM cores · ARM Cortex-A · ARM Cortex-R · ARM Cortex-M · Comparison of ARMv7-A cores · Comparison of ARMv8-A cores [hide]	
Application processors (32-bit)	Cortex-A5	Actions ATM702x · Amlogic M805/S805, T82x · Atmel SAMA5D3 · InfoTM iMAPx820, iMAPx15 · Qualcomm Snapdragon S4 Play, 200 · RDA RDA8810PL · Telechips TCC892x	
	Cortex-A7	Allwinner A2x, A3x, A83T, H3, H8 · Broadcom VideoCore BCM2836, BCM23550 · Freescale QorIQ LS10xx · Leadcore LC1813, LC1860/C, LC1913, LC1960 · Marvell Armada PXA1920 · MediaTek MT65xx · Qualcomm Snapdragon 200, 400	
	Cortex-A8	Allwinner A1x · Apple A4 · Freescale i.MX5 · Rockchip RK291x · Samsung Exynos 3110(S5PC110), S5PV210 · Texas Instruments OMAP 3 · ZiiLABS ZMS-08	
	Cortex-A9	Actions ATM702x, ATM703x · Altera Cyclone V, Arria VI/10 · Amlogic AML8726, MX, M6x, M801, M802/S802, S812, T86x · Apple A5, A5X · Broadcom VideoCore BCM21xxx, BCM28xxx · Freescale i.MX6 · HiSilicon K3V2, 910's · InfoTM iMAPx912 · Leadcore LC1810, LC1811 · MediaTek MT65xx · Nvidia Tegra 2, 3, 4i · Nufront NuSmart 2816M, NS115, NS115M · Renesas EMMA EV2, R-Car H1, RZA · Rockchip RK292x, RK30xx, RK31xx · Samsung Exynos 4 421x, 441x · ST-Ericsson NovaThor · Telechips TCC8803 · Texas Instruments OMAP 4 · VIA WonderMedia WM88x0, 89x0 · Xilinx Zynq-7000 · ZiiLABS ZMS-20, ZMS-40	
	Cortex-A15	Allwinner A80 · HiSilicon K3V3 · MediaTek MT8135/V · Nvidia Tegra 4, K1 · Renesas R-Car H2 · Samsung Exynos 5 52xx, 54xx · Texas Instruments OMAP 5, DRA7xx, AM57xx	
	Cortex-A17	MediaTek MT6595, MT5595 · Mstar 6A928 · Rockchip RK3288	
	ARMv7-A compatible	Apple A6, A6X, S1 · Broadcom Brahma-B15 · Marvell P4J · Qualcomm Snapdragon S1, S2, S3, S4 Plus, S4 Pro, 600, 800 (Scorpion, Krait)	
	Cortex-A53	Actions GT7, S900, V700 · Allwinner A64, H5, H64, R18 · Altera Stratix 10 · Amlogic S9 Family, T96x · Broadcom BCM2837 · EZchip TILE-Mx100 · HiSilicon Kirin 620, 65x, 93x · Marvell Armada PXA1928, Mobile PXA1908/PXA1936 · MediaTek MT673x, MT675x, MT6795, MT873x, MT8752, MT8163 · NXP ARM S32 · Qualcomm Snapdragon 41x, 42x, 43x, 61x, 62x · Rockchip RK3328, RK3368 · Samsung Exynos 7 75xx, 78xx · Spreadtrum SC9860/GV, SC9836 · Xilinx ZynqMP	
Application processors (64-bit)	Cortex-A57	AMD Opteron A1100-series · Freescale QorIQ LS20xx · Nvidia Tegra X1 · Qualcomm Snapdragon 808, 810 · Samsung Exynos 7 5433, 7420	
	Cortex-A72	HiSilicon Kirin 95x · MediaTek Helio X2x, MT817x · Mstar 6A938 · Qualcomm Snapdragon 65x · Rockchip RK3399	
	Cortex-A73	HiSilicon Kirin 960 · MediaTek Helio X30	
	Cortex-A75	Qualcomm Snapdragon 845	
	ARMv8-A compatible	Apple A7 to A10 · Applied Micro X-Gene · Cavium ThunderX CN87xx, CN88xx · Nvidia Tegra K1 (Project Denver) · Samsung Mongoose · NXP i.MX 8 · Qualcomm Kryo · Qualcomm Falkor	

[WIKIPEDIA, 2020-b]

<https://www.anandtech.com/show/14644/arm-flexible-access-design-the-soc-before-spending-money>

Fatia de Mercado



[STATISTA, 2022]



Mercado
Financeiro

QUALCOMM®



AMD



2004-2022

intel®



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